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New 8FX 8-bit Microcontrollers

The MB95560H/570H/580H is a series of general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers of this series contain a variety of peripheral resources.

Features

- F²MC-8FX CPU core
 - Instruction set optimized for controllers
 - · Multiplication and division instructions
 - · 16-bit arithmetic operations
 - · Bit test branch instructions
 - Bit manipulation instructions, etc.
- Clock (The main oscillation clock and the suboscillation clock are only available on MB95F562H/F562K/F563H/F563K/ F564H/F564K/F582H/F582K/F583H/F583K/F584H/F584K.)
 - Selectable main clock source
 - Main oscillation clock (up to 16.25 MHz, maximum machine clock frequency: 8.125 MHz)
 - External clock (up to 32.5 MHz, maximum machine clock frequency: 16.25 MHz)
 - Main CR clock (4 MHz ± 2%)
 - The main CR clock frequency becomes 8 MHz when the PLL multiplication rate is 2.
 - The main CR clock frequency becomes 10 MHz when the PLL multiplication rate is 2.5.
 - The main CR clock frequency becomes 12 MHz when the PLL multiplication rate is 3.
 - The main CR clock frequency becomes 16 MHz when the PLL multiplication rate is 4.
 - □Selectable subclock source
 - Suboscillation clock (32.768 kHz)
 - External clock (32.768 kHz)
 - Sub-CR clock (Typ: 100 kHz, Min: 50 kHz, Max: 150 kHz)
- Timer
 - 8/16-bit composite timer × 2 channels (only one channel on MB95F572H/F572K/F573H/F573K/F574H/F574K/F582H/ F582K/F583H/F583K/F584H/F584K)
 - □ Time-base timer × 1 channel
 - □ Watch prescaler × 1 channel
- LIN-UART (only available on MB95F562H/F562K/F563H/ F563K/F564H/F564K/F582H/F582K/F583H/F583K/F584H/ F584K)
 - Full duplex double buffer
 - Capable of clock synchronous serial data transfer and clock asynchronous serial data transfer
- External interrupt
 - Interrupt by edge detection (rising edge, falling edge, and both edges can be selected)
 - Can be used to wake up the device from different low power consumption (standby) modes
- 8/10-bit A/D converter
 8-bit or 10-bit resolution can be selected.
- Low power consumption (standby) modes

- □ There are four standby modes as follows:
 - Stop mode
 - Sleep mode
- Watch mode
- · Time-base timer mode
- In standby mode, the device can be made to enter either normal standby mode or deep standby mode.
- I/O port
 - □ MB95F562H/F563H/F564H (maximum no. of I/O ports: 16)
 - General-purpose I/O ports (CMOS I/O): 15
 - General-purpose I/O ports (N-ch open drain): 1
 - MB95F562K/F563K/F564K (maximum no. of I/O ports: 17)
 General-purpose I/O ports (CMOS I/O): 15
 - General-purpose I/O ports (N-ch open drain): 2
 - □ MB95F572H/F573H/F574H (maximum no. of I/O ports: 4)
 - General-purpose I/O ports (CMOS I/O): 3
 - General-purpose I/O ports (N-ch open drain): 1
 - MB95F572K/F573K/F574K (maximum no. of I/O ports: 5)
 General-purpose I/O ports (CMOS I/O): 3
 - General-purpose I/O ports (N-ch open drain): 2
 - MB95F582H/F583H/F584H (maximum no. of I/O ports: 12)
 General-purpose I/O ports (CMOS I/O): 11
 - General-purpose I/O ports (N-ch open drain): 1
 - MB95F582K/F583K/F584K (maximum no. of I/O ports: 13)
 General-purpose I/O ports (CMOS I/O): 11
 - General-purpose I/O ports (N-ch open drain): 2
- On-chip debug
 - 1-wire serial control
 - Serial writing supported (asynchronous mode)
- Hardware/software watchdog timer
 Built-in hardware watchdog timer
 Built-in software watchdog timer
- Power-on reset
 - \square A power-on reset is generated when the power is switched on.
- Low-voltage detection reset circuit (only available on MB95F562K/F563K/F564K/F572K/F573K/F574K/F582K/ F583K/F584K)
 Digital in low contents
 - Built-in low-voltage detector
- Clock supervisor counter
 Built-in clock supervisor counter function
- Dual operation Flash memory
- The program/erase operation and the read operation can be executed in different banks (upper bank/lower bank) simultaneously.
- Flash memory security function
 - Protects the content of the Flash memory.

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MB95560H Series MB95570H Series MB95580H Series

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1. Product Line-up

MB95560H Series

Part number	Genes							
	MB95F562H	MB95F563H	MB95F564H	MB95F562K	MB95F563K	MB95F564K		
Parameter								
Туре			Flash mem	ory product		1		
Clock				71				
supervisor	It supervises th	e main clock os	scillation.					
counter								
Flash memory	0 Khuta	10 1/1-1-	00 1/1-1-1-	0 1/1-1-1-	10 1/1-1-	00 1/1-1-		
capacity	8 Kbyte	12 Kbyte	20 Kbyte	8 Kbyte	12 Kbyte	20 Kbyte		
RAM capacity	240 bytes	496 bytes	496 bytes	240 bytes	496 bytes	496 bytes		
Power-on reset	-		Y	es		-		
Low-voltage		No			Yes			
detection reset		INO			165			
Reset input		Dedicated		Selec	cted through sof	tware		
	 Number of bat 	asic instructions	: 136					
	 Instruction bit 		: 8 bits					
	 Instruction let 	0	: 1 to 3					
	 Data bit lengt 			nd 16 bits				
					ck frequency = [·]			
	 Interrupt proc 		: 0.6 µs		<pre>k frequency = 16</pre>	6.25 MHz)		
General-	• I/O ports (Max) : 16 • I/O ports (Max) : 17							
nurnose I/O	• CMOS I/O : 15 • CMOS I/O : 15							
	 N-ch open dr 			 N-ch open dr 				
Time-base timer			s (external clock	r frequency = 4	MHz)			
	Reset generation							
software			MHz: 105 ms (
	The sub-CR			e clock of the h	ardware watcho	log timer.		
	It can be used							
				be selected by a	a dedicated relo	ad timer.		
	 It has a full division 	•			hunnesse neutral d	ata tuanafan ana		
LIN-UART	 Both clock synchronous serial data transfer and clock asynchronous serial data transfer are enabled. 							
	 The LIN func 	tion can be use		or or o LIN alou	10			
	6 channels	uon can be use	u as a Lin mas		e.			
	8-bit or 10-bit r	esolution can be	a selected					
	2 channels		e selected.					
		he configured	as an "8-hit time	$r \times 2$ channels"	or a "16-bit tim	er × 1 channel"		
						nction and input		
composite timer		•				iotion and input		
			ed from internal	clocks (7 types) and external o	clocks.		
	 It can output 				, and external t			
	6 channels							
External		dge detection (The rising edge	, falling edge. o	r both edges ca	n be selected.)		
interrupt	 It can be use 	0 (0 0		0			
	 1-wire serial 			,				
()n_chin dahua			nchronous mod	le).				
• It supports serial writing (asynchronous mode).								



Part number Parameter	MB95F562H	MB95F563H	MB95F564H	MB95	F562K	MB95F563K	MB95F564K
Watch prescaler	Eight different t	ime intervals ca	an be selected.				
	suspend/eras • It has a flag in • Flash securit Number of	It supports automatic programming (Embedded Algorithm), and program/erase/erasesuspend/erase-resume commands.It has a flag indicating the completion of the operation of Embedded Algorithm.Flash security feature for protecting the content of the Flash memoryNumber of program/erase cycles100010000100000Data retention time20 years10 years5 years					
Standby mode	Sleep mode, stop mode, watch mode, time-base timer mode						
Package			SO	-032 J020 G020			

• MB95570H Series

	• MB95570H Series								
Part number		MDOCECTOL	MDOSESZALI	MDAEFEZOK	MDOCECTOK	MDOCESTAK			
Parameter	MB95F572H	MB95F573H	MB95F574H	MB95F572K	MB95F573K	MB95F574K			
Type		Flash memory product							
Clock			r lasir mem	ory product					
supervisor	It supervises th	e main clock os	scillation						
counter			Somation.						
Flash memory									
capacity	8 Kbyte	12 Kbyte	20 Kbyte	8 Kbyte	12 Kbyte	20 Kbyte			
RAM capacity	240 bytes	496 bytes	496 bytes	240 bytes	496 bytes	496 bytes			
Power-on reset	_	-	Y	es	_	-			
Low-voltage		No			Yes				
detection reset		INO			165				
Reset input		Dedicated		Selec	ted through sof	tware			
	Number of basic instructions : 136								
	Instruction bit length : 8 bits								
CPU functions	Instruction length : 1 to 3 bytes								
	0	Data bit length : 1, 8 and 16 bits							
			on time :61.5 n						
	 Interrupt proc 		: 0.6 µs		k frequency = 16	6.25 MHz)			
General-	 I/O ports (Ma 			 I/O ports (Ma 	,				
purpose I/O	CMOS I/O	: 3		 CMOS I/O 	: 3				
r ·	 N-ch open dr 			 N-ch open dr 					
Time-base timer			s (external clock	frequency = 4	MHz)				
	 Reset generation 								
software			MHz: 105 ms (
		The sub-CR clock can be used as the source clock of the hardware watchdog timer.							
Wild register	It can be used	to replace 3 byt	es of data.						
LIN-UART	No LIN-UART								
8/10-bit A/D	2 channels								
converter	8-bit or 10-bit r	esolution can be	e selected.						



Part number	MB95E572H	MB95F572H MB95F573H MB95F574H MB95F572K MB95F573K MB95F						
Parameter				MBSOI	0721			
8/16-bit composite timer	 It has the follo capture funct Count clock: 	channel The timer can be configured as an "8-bit timer × 2 channels" or a "16-bit timer × 1 channel". It has the following functions: interval timer function, PWC function, PWM function and input capture function. Count clock: it can be selected from internal clocks (7 types) and external clocks. It can output square wave.						
External interrupt	2 channels • Interrupt by e • It can be use	dge detection (d to wake up th					n be selected.)	
On_chin debug	 1-wire serial of It supports serial 		nchronous mod	le).				
Watch prescaler	•							
	•	se-resume comindicating the co	mands. mpletion of the	operatio	n of Emb	bedded Algorit		
	Number of	program/erase	cycles 1	000	10000	100000		
	Data retention time20 years10 years5 years							
Standby mode	Sleep mode, st	Sleep mode, stop mode, watch mode, time-base timer mode						
Package				A008 D008				

MB95580H Series

Part number							
	MB95F582H	MB95F582H MB95F583H MB95F584H M		MB95F582K	MB95F583K	MB95F584K	
Parameter							
Туре			Flash mem	ory product			
Clock supervisor counter	It supervises th	supervises the main clock oscillation.					
Flash memory capacity	8 Kbyte	12 Kbyte	20 Kbyte	8 Kbyte	12 Kbyte	20 Kbyte	
RAM capacity	240 bytes	496 bytes	496 bytes	240 bytes	496 bytes	496 bytes	
Power-on reset			Y	es	•		
Low-voltage		No			Yes		
detection reset		NO			165		
Reset input		Dedicated		Selec	cted through sof	ftware	
	 Number of ba Instruction bit Instruction let 	length	: 136 : 8 bits : 1 to 3	bvtes			
CPU functions	 Data bit lengt 	•		nd 16 bits			
	•		on time :61.5 n		ck frequency = [·]	16.25 MHz)	
	 Interrupt proc 	essing time	: 0.6 µs	(machine clock	k frequency = 10	6.25 MHz)	
General- purpose I/O	 I/O ports (Ma CMOS I/O N-ch open dr 	: 11		 I/O ports (Ma CMOS I/O N-ch open dr 	: 11		



Part number								
	MB95F582H	MB95F583H	MB95F584H	MB95	5F582K	MB95F583K	MB95F584K	
Parameter	nterval time: 0.256 ms to 8.3 s (external clock frequency = 4 MHz)							
			s (external clo	k freque	ency = 4	MHz)		
	Reset generation							
software watchdog timer		tion clock at 10			of the b	ordworo wotobo	log timor	
-							log umer.	
,	It can be used t			ha aala			ad time an	
		uplex double bu nchronous seria	iffer. al data transfe	and cloo	ck asyncl	hronous serial c	ad umer. lata transfer are	
8/10-bit A/D	5 channels							
converter	8-bit or 10-bit re	esolution can be	e selected.					
	1 channel							
composite timer	 It has the follo capture funct Count clock: It can output 	ion. it can be selecte	interval timer	function,	, PWC fu	nction, PWM fu	nction and input	
External	6 channels							
interrupt	 Interrupt by e It can be use 						n be selected.)	
On-chip debug	1-wire serial ofIt supports serial		nchronous m	ode).				
Watch prescaler	Eight different t	ime intervals ca	n be selected					
Flash memory	 It supports automatic programming (Embedded Algorithm), and program/erase/erase-suspend/erase-resume commands. It has a flag indicating the completion of the operation of Embedded Algorithm. Flash security feature for protecting the content of the Flash memory 							
	Number of	program/erase	cycles	1000	1000	0 100000		
	Data retention time20 years10 years5 years							
Standby mode	Sleep mode, stop mode, watch mode, time-base timer mode							
Package			WI S ⁻	IP032 B016 D016				



2. Packages And Corresponding Products

MB95560H Series

Part number Package	MB95F562H	MB95F562K	MB95F563H	MB95F563K	MB95F564H	MB95F564K
WNP032	0	0	0	0	0	0
SOJ020	0	0	0	0	0	0
STG020	0	0	0	0	0	0
STB016	Х	Х	Х	Х	Х	Х
SO016	Х	Х	Х	Х	Х	Х
PDA008	Х	Х	Х	Х	Х	Х
SOD008	Х	Х	Х	Х	Х	Х

MB95570H Series

Part number Package	MB95F572H	MB95F572K	MB95F573H	MB95F573K	MB95F574H	MB95F574K
WNP032	Х	Х	Х	Х	Х	Х
SOJ020	Х	Х	Х	Х	Х	Х
STG020	Х	Х	Х	Х	Х	Х
STB016	Х	Х	Х	Х	Х	Х
SO016	Х	Х	Х	Х	Х	Х
PDA008	0	0	0	0	0	0
SOD008	0	0	0	0	0	0

• MB95580H Series

Part number Package	MB95F582H	MB95F582K	MB95F583H	MB95F583K	MB95F584H	MB95F584K
WNP032	0	0	0	0	0	0
SOJ020	Х	Х	Х	Х	Х	Х
STG020	Х	Х	Х	Х	Х	Х
STB016	0	0	0	0	0	О
SO016	0	0	0	0	0	О
PDA008	Х	Х	Х	Х	Х	Х
SOD008	Х	Х	Х	Х	Х	Х

O: Available

X: Unavailable



3. Differences Among Products And Notes On Product Selection

Current consumption

When using the on-chip debug function, take account of the current consumption of Flash memory program/erase. For details of current consumption, see "Electrical Characteristics".

Package

For details of information on each package, see "Packages And Corresponding Products" and "Package Dimension".

· Operating voltage

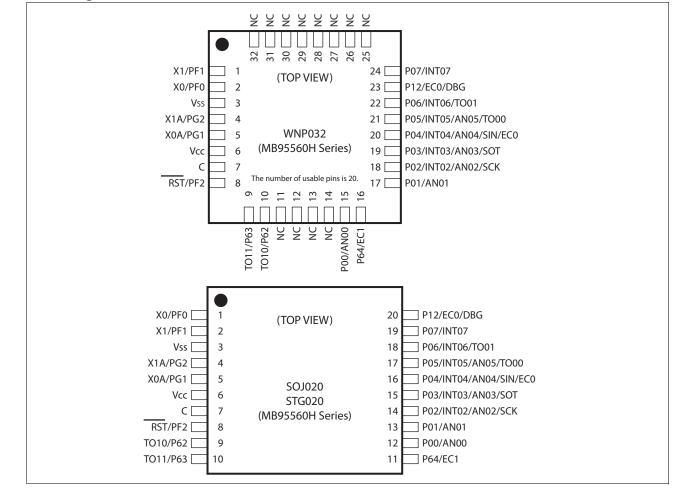
The operating voltage varies, depending on whether the on-chip debug function is used or not. For details of the operating voltage, see "Electrical Characteristics".

• On-chip debug function

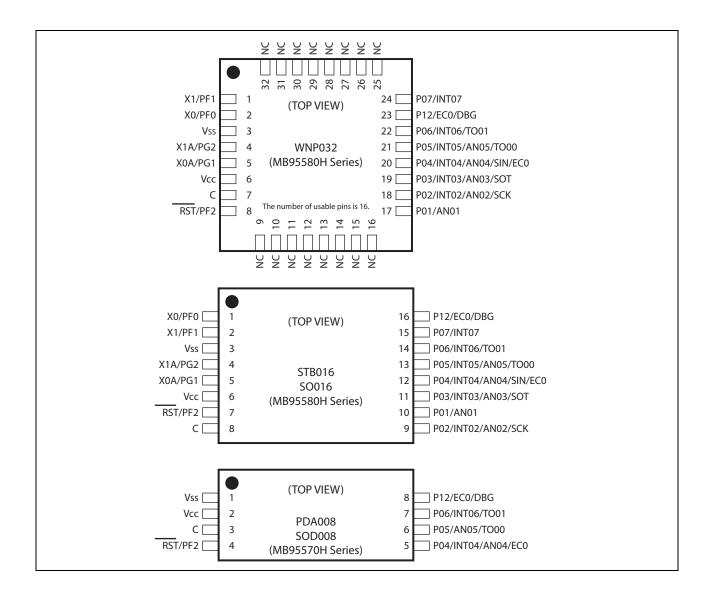
The on-chip debug function requires that V_{CC}, V_{SS} and one serial wire be connected to an evaluation tool. For details of the connection method, refer to "CHAPTER 21 EXAMPLE OF SERIAL PROGRAMMING CONNECTION" in "New 8FX MB95560H/570H/580H Hardware Manual".



4. Pin Assignment









5. Pin Functions (MB95560H Series, 32 pins)

Pin no.	Pin name	I/O circuit type*	Function
1	PF1	В	General-purpose I/O port
	X1		Main clock I/O oscillation pin
2	PF0	В	General-purpose I/O port
	X0		Main clock input oscillation pin
3	Vss	—	Power supply pin (GND)
4	PG2	с	General-purpose I/O port
7	X1A	U	Subclock I/O oscillation pin
5	PG1	- c	General-purpose I/O port
	X0A	Ŭ	Subclock input oscillation pin
6	Vcc	—	Power supply pin
7	С	—	Decoupling capacitor connection pin
	PF2		General-purpose I/O port
8	RST	Α	Reset pin
	T(O)		Dedicated reset pin on MB95F562H/F563H/F564H
	P63		General-purpose I/O port
9		E	High-current pin
	TO11		8/16-bit composite timer ch. 1 output pin
	P62		General-purpose I/O port
10	-	E	High-current pin
	TO10		8/16-bit composite timer ch. 1 output pin
11 12 13 14	NC	_	It is an internally connected pin. Always leave it unconnected.
	P00		General-purpose I/O port
15		D	High-current pin
	AN00		A/D converter analog input pin
	P64		General-purpose I/O port
16	-	E	High-current pin
	EC1		8/16-bit composite timer ch. 1 clock input pin
	P01		General-purpose I/O port
17		D	High-current pin
	AN01		A/D converter analog input pin
	P02		General-purpose I/O port
		↓ _	High-current pin
18	INT02	D	External interrupt input pin
	AN02	4	A/D converter analog input pin
	SCK		LIN-UART clock I/O pin



Pin no.	Pin name	I/O circuit type*	Function
	P03		General-purpose I/O port
	F03		High-current pin
19	INT03	D	External interrupt input pin
	AN03		A/D converter analog input pin
	SOT		LIN-UART data output pin
	P04		General-purpose I/O port
	INT04		External interrupt input pin
20	AN04	D	A/D converter analog input pin
	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
	P05		General-purpose I/O port
	F03		High-current pin
21	INT05	D	External interrupt input pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
	P06		General-purpose I/O port
22		Ε	High-current pin
22	INT06		External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
	P12		General-purpose I/O port
23	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin
	P07		General-purpose I/O port
24		E	High-current pin
	INT07		External interrupt input pin
25			
26			
27			
28	NC		It is an internally connected pin. Always leave it unconnected.
29	NO		n io an internally connected pin. Always leave it unconnected.
30			
31			
32			

*: For the I/O circuit types, see "I/O Circuit Type".



6. Pin Functions (MB95560H Series, 20 pins)

Pin no.	Pin name	I/O circuit type*	Function
1	PF0	В	General-purpose I/O port
1	X0		Main clock input oscillation pin
2	PF1	В	General-purpose I/O port
	X1		Main clock I/O oscillation pin
3	Vss	—	Power supply pin (GND)
4	PG2	с	General-purpose I/O port
-	X1A	U	Subclock I/O oscillation pin
5	PG1	С	General-purpose I/O port
	X0A	U	Subclock input oscillation pin
6	Vcc	—	Power supply pin
7	С	—	Decoupling capacitor connection pin
	PF2		General-purpose I/O port
8	RST	Α	Reset pin
	NOT		Dedicated reset pin on MB95F562H/F563H/F564H
	P62		General-purpose I/O port
9		E	High-current pin
	TO10		8/16-bit composite timer ch. 1 output pin
	P63		General-purpose I/O port
10		E	High-current pin
	TO11		8/16-bit composite timer ch. 1 output pin
	P64		General-purpose I/O port
11	-	E	High-current pin
	EC1		8/16-bit composite timer ch. 1 clock input pin
	P00		General-purpose I/O port
12		D	High-current pin
	AN00		A/D converter analog input pin
	P01		General-purpose I/O port
13	-	D	High-current pin
	AN01		A/D converter analog input pin
	P02		General-purpose I/O port
			High-current pin
14	INT02	D	External interrupt input pin
	AN02	_	A/D converter analog input pin
	SCK		LIN-UART clock I/O pin
	P03		General-purpose I/O port
		1	High-current pin
15	INT03	D	External interrupt input pin
	AN03	1	A/D converter analog input pin
	SOT		LIN-UART data output pin





Pin no.	Pin name	I/O circuit type*	Function
	P04		General-purpose I/O port
	INT04	1	External interrupt input pin
16	AN04	D	A/D converter analog input pin
	SIN	1	LIN-UART data input pin
	EC0	1	8/16-bit composite timer ch. 0 clock input pin
	DOF		General-purpose I/O port
	P05		High-current pin
17	INT05	D	External interrupt input pin
	AN05	1	A/D converter analog input pin
	TO00	1	8/16-bit composite timer ch. 0 output pin
	DOG		General-purpose I/O port
10	P06	E	High-current pin
18	INT06		External interrupt input pin
	TO01	1	8/16-bit composite timer ch. 0 output pin
	P07		General-purpose I/O port
19	P07	E	High-current pin
	INT07	1	External interrupt input pin
	P12		General-purpose I/O port
20	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG	1	DBG input pin

*: For the I/O circuit types, see "I/O Circuit Type".



7. Pin Functions (MB95570H Series, 8 pins)

Pin no.	Pin name	I/O circuit type*	Function			
1	Vss	—	Power supply pin (GND)			
2	Vcc	—				
3	С	—	Power supply pin (GND)Power supply pinDecoupling capacitor connection pinGeneral-purpose I/O portReset pinDedicated reset pin on MB95F572H/F573H/F574HGeneral-purpose I/O portExternal interrupt input pinA/D converter analog input pin8/16-bit composite timer ch. 0 clock input pinGeneral-purpose I/O portHigh-current pinA/D converter analog input pin8/16-bit composite timer ch. 0 output pinGeneral-purpose I/O portHigh-current pinA/D converter analog input pin8/16-bit composite timer ch. 0 output pinGeneral-purpose I/O portHigh-current pin8/16-bit composite timer ch. 0 output pinGeneral-purpose I/O portHigh-current pinExternal interrupt input pin8/16-bit composite timer ch. 0 output pinGeneral-purpose I/O port8/16-bit composite timer ch. 0 output pinGeneral-purpose I/O port8/16-bit composite timer ch. 0 output pin8/16-bit composite timer ch. 0 clock input pin			
	PF2		General-purpose I/O port			
4	RST	A				
	P04		General-purpose I/O port			
5	INT04	D	External interrupt input pin			
5	AN04		A/D converter analog input pin			
	EC0		8/16-bit composite timer ch. 0 clock input pin			
	P05					
6	AN05	D	A/D converter analog input pin			
	TO00		8/16-bit composite timer ch. 0 output pin			
7	P06	_				
7	INT06	E	External interrupt input pin			
	TO01		8/16-bit composite timer ch. 0 output pin			
	P12		General-purpose I/O port			
8	EC0	F	8/16-bit composite timer ch. 0 clock input pin			
	DBG		DBG input pin			

*: For the I/O circuit types, see "I/O Circuit Type".



8. Pin Functions (MB95580H Series, 32 pins)

Pin no.	Pin name	I/O circuit type*	Function					
1	PF1	B	General-purpose I/O port					
	X1	D	Main clock I/O oscillation pin					
2	PF0	В	General-purpose I/O port					
2	X0		General-purpose I/O port					
3	Vss	—	Power supply pin (GND) General-purpose I/O port					
4	PG2	с	General-purpose I/O port					
4	X1A		Subclock I/O oscillation pin					
5	PG1	С	General-purpose I/O port					
5	X0A		Subclock input oscillation pin					
6	Vcc	—	Power supply pin					
7	С	—	Decoupling capacitor connection pin					
	PF2		General-purpose I/O port					
8	RST	A	Reset pin Dedicated reset pin on MB95F582H/F583H/F584H					
9								
10								
11		_						
12	NC		It is an internally connected pin. Always leave it unconnected.					
13	No							
14								
15								
16								
17	P01	D	General-purpose I/O port High-current pin					
	AN01		A/D converter analog input pin					
	P02		General-purpose I/O port High-current pin					
18	INT02	D	External interrupt input pin					
	AN02]	A/D converter analog input pin					
	SCK		LIN-UART clock I/O pin					
	P03		General-purpose I/O port High-current pin					
19	INT03	D	External interrupt input pin					
	AN03]	A/D converter analog input pin					
	SOT		LIN-UART data output pin					





Pin no.	Pin name	I/O circuit type*	Function
	P04		General-purpose I/O port
-	INT04		External interrupt input pin
20	AN04	D	A/D converter analog input pin
-	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
	P05		General-purpose I/O port High-current pin
21	INT05	D	External interrupt input pin
	AN05		A/D converter analog input pin
	ТО00		8/16-bit composite timer ch. 0 output pin
	P06		General-purpose I/O port High-current pin
22	INT06	E	External interrupt input pin
-	TO01		8/16-bit composite timer ch. 0 output pin
	P12		General-purpose I/O port
23	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin
24	P07	E	General-purpose I/O port High-current pin
-	INT07		External interrupt input pin
25			
26			
27			
28	NC		It is an internally connected pin. Always leave it unconnected.
29	NO		n is an internally connected pin. Always leave it unconnected.
30			
31			
32			

*: For the I/O circuit types, see "I/O Circuit Type".



9. Pin Functions (MB95580H Series, 16 pins)

Pin no.	Pin name	I/O circuit type*	Function
4	PF0	Р	General-purpose I/O port
1 -	X0	- В	Main clock input oscillation pin
2	PF1	В	General-purpose I/O port
2	X1		Main clock I/O oscillation pin
3	Vss	_	Power supply pin (GND)
4	PG2	с	General-purpose I/O port
4	X1A		Subclock I/O oscillation pin
5 –	PG1	С	General-purpose I/O port
5	X0A		Subclock input oscillation pin
6	Vcc	—	Power supply pin
	PF2		General-purpose I/O port
7	RST	A	Reset pin Dedicated reset pin on MB95F582H/F583H/F584H
8	С	_	Decoupling capacitor connection pin
	P02		General-purpose I/O port High-current pin
9	INT02	D	External interrupt input pin
	AN02		A/D converter analog input pin
	SCK		LIN-UART clock I/O pin
10	P01	D	General-purpose I/O port High-current pin
	AN01	1	A/D converter analog input pin
	P03		General-purpose I/O port High-current pin
11	INT03	D	External interrupt input pin
	AN03	1	A/D converter analog input pin
	SOT		LIN-UART data output pin
	P04		General-purpose I/O port
	INT04	1	External interrupt input pin
12	AN04	D	A/D converter analog input pin
	SIN]	LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin



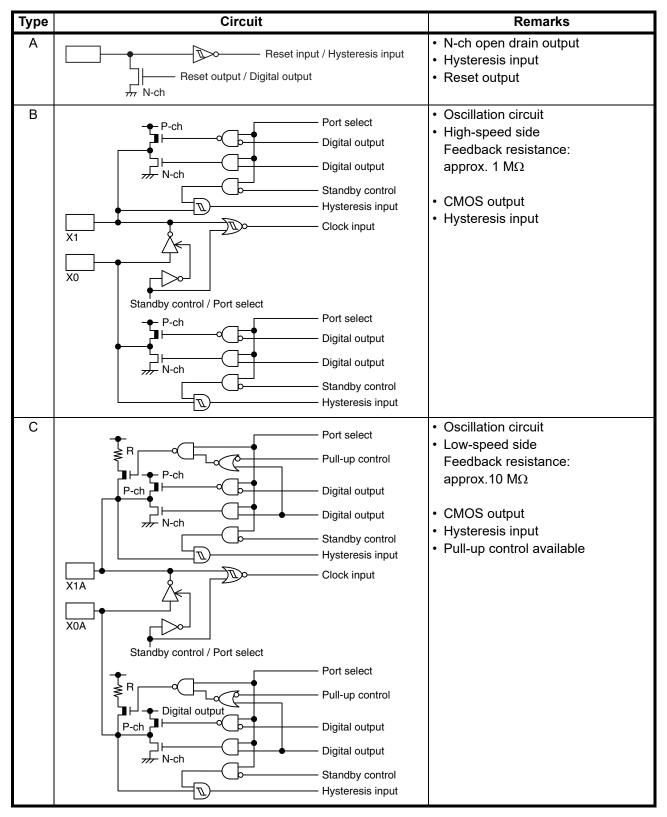


Pin no.	Pin name	I/O circuit type*	Function
	P05		General-purpose I/O port High-current pin
13	INT05	D	External interrupt input pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
	P06		General-purpose I/O port High-current pin
14	INT06	E	External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
15	P07	E	General-purpose I/O port High-current pin
	INT07	Ī	External interrupt input pin
	P12		General-purpose I/O port
16	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin

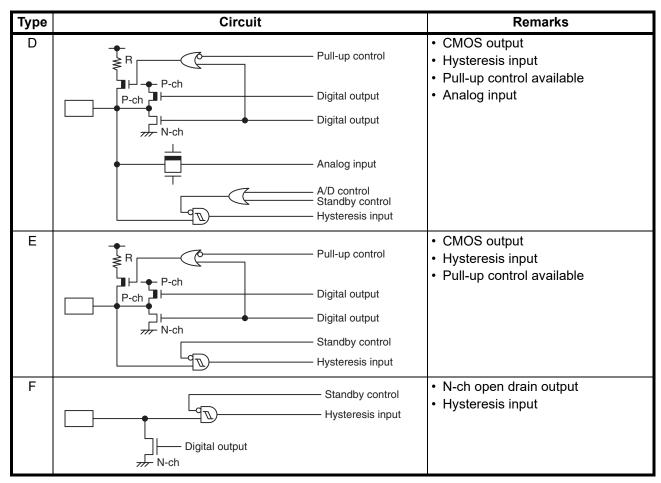
*: For the I/O circuit types, see "I/O Circuit Type".



10. I/O Circuit Type







11. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

11.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative before-hand.



Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

(1) Preventing Over-Voltage and Over-Current Conditions

Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

(2) Protection of Output Pins

Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.

Therefore, avoid this type of connection.

(3) Handling of Unused Input Pins

Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

• Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

- (1) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
- (2) Be sure that abnormal current flows do not occur during the power-on sequence.

Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

• Precautions Related to Usage of Devices

Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.



11.2 Precautions for Package Mounting

Package mounting may be either lead insertion type or surface mount type. In either case, for heat resistance during soldering, you should only mount under Cypress's recommended conditions. For detailed information about mount conditions, contact your sales representative.

• Lead Insertion Type

Mounting of lead insertion type packages onto printed circuit boards may be done by two methods: direct soldering on the board, or mounting by using a socket.

Direct mounting onto boards normally involves processes for inserting leads into through-holes on the board and using the flow soldering (wave soldering) method of applying liquid solder. In this case, the soldering process usually causes leads to be subjected to thermal stress in excess of the absolute ratings for storage temperature. Mounting processes should conform to Cypress recommended mounting conditions.

If socket mounting is used, differences in surface treatment of the socket contacts and IC lead surfaces can lead to contact deterioration after long periods. For this reason it is recommended that the surface treatment of socket contacts and IC leads be verified before mounting.

• Surface Mount Type

Surface mount packaging has longer and thinner leads than lead-insertion packaging, and therefore leads are more easily deformed or bent. The use of packages with higher pin counts and narrower pin pitch results in increased susceptibility to open connections caused by deformed pins, or shorting due to solder bridges.

You must use appropriate mounting techniques. Cypress recommends the solder reflow method, and has established a ranking of mounting conditions for each product. Users are advised to mount packages in accordance with Cypress ranking of recommended conditions.

• Lead-Free Packaging

CAUTION: When ball grid array (BGA) packages with Sn-Ag-Cu balls are mounted using Sn-Pb eutectic soldering, junction strength may be reduced under some conditions of use.

Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

- (1) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.
- (2) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.

When you open Dry Package that recommends humidity 40% to 70% relative humidity.

- (3) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.
- (4) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:



- (1) Maintain relative humidity in the working environment between 40% and 70%.
 - Use of an apparatus for ion generation may be needed to remove electricity.
- (2) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
- (3) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 M Ω).

Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.

- (4) Ground all fixtures and instruments, or protect with anti-static measures.
- (5) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

11.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

(1) Humidity

Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.

(2) Discharge of Static Electricity

When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.

(3) Corrosive Gases, Dust, or Oil

Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.

(4) Radiation, Including Cosmic Radiation

Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.

(5) Smoke, Flame

CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

12. Notes On Device Handling

Preventing latch-ups

When using the device, ensure that the voltage applied does not exceed the maximum voltage rating.

In a CMOS IC, if a voltage higher than Vcc or a voltage lower than Vss is applied to an input/output pin that is neither a medium-withstand voltage pin nor a high-withstand voltage pin, or if a voltage out of the rating range of power supply voltage mentioned in "24.1 Absolute Maximum Ratings" of "Electrical Characteristics" is applied to the Vcc pin or the Vss pin, a latch-up may occur.

When a latch-up occurs, power supply current increases significantly, which may cause a component to be thermally destroyed.

• Stabilizing supply voltage



Supply voltage must be stabilized.

A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the Vcc power supply voltage.

As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in V_{cc} ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard V_{cc} value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

• Notes on using the external clock

When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from subclock mode or stop mode.

13. Pin Connection

• Treatment of unused pins

If an unused input pin is left unconnected, a component may be permanently damaged due to malfunctions or latchups. Always pull up or pull down an unused input pin through a resistor of at least 2 k Ω . Set an unused input/output pin to the output state and leave it unconnected, or set it to the input state and treat it the same as an unused input pin. If there is an unused output pin, leave it unconnected.

· Power supply pins

To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the V_{CC} pin and the V_{SS} pin to the power supply and ground outside the device. In addition, connect the current supply source to the V_{CC} pin and the V_{SS} pin with low impedance.

It is also advisable to connect a ceramic capacitor of approximately 0.1 μ F as a decoupling capacitor between the V_{cc} pin and the V_{ss} pin at a location close to this device.

DBG pin

Connect the DBG pin to an external pull-up resistor of 2 k Ω or above.

After power-on, ensure that the DBG pin does not stay at "L" level until the reset output is released.

The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

RST pin

Connect the $\overline{\text{RST}}$ pin to an external pull-up resistor of 2 k Ω or above.

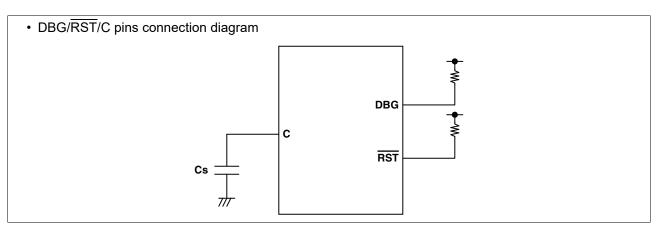
To prevent the device from unintentionally entering the reset mode due to noise, minimize the interconnection length between a pull-up resistor and the RST pin and that between a pull-up resistor and the Vcc pin when designing the layout of the printed circuit board.

The PF2/RST pin functions as the reset input/output pin after power-on. In addition, the reset output of the PF2/RST pin can be enabled by the RSTOE bit in the SYSC register, and the reset input function and the general purpose I/O function can be selected by the RSTEN bit in the SYSC register.

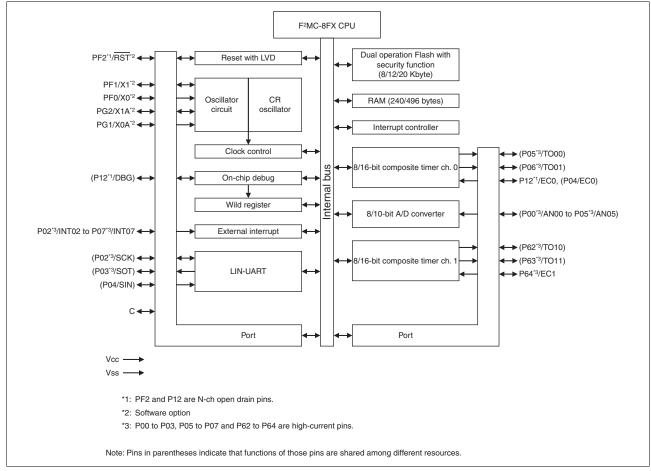
• C pin

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_s . For the connection to a decoupling capacitor C_s , see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and C_s and the distance between C_s and the Vss pin when designing the layout of a printed circuit board.



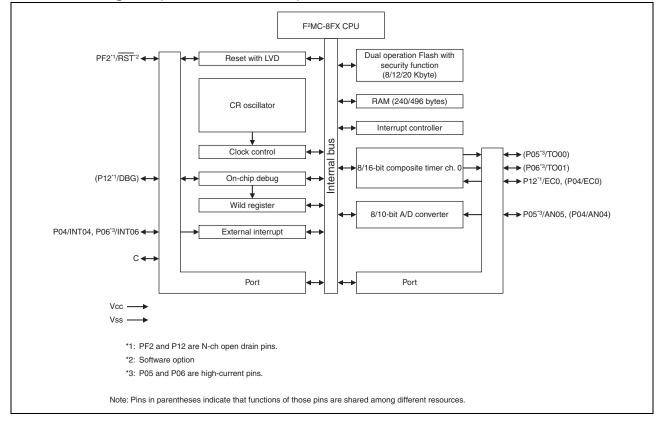


14. Block Diagram (MB95560H Series)



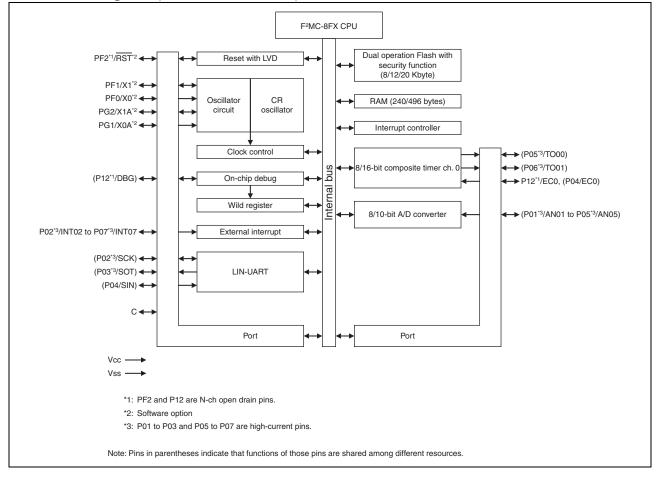


15. Block Diagram (MB95570H Series)





16. Block Diagram (MB95580H Series)



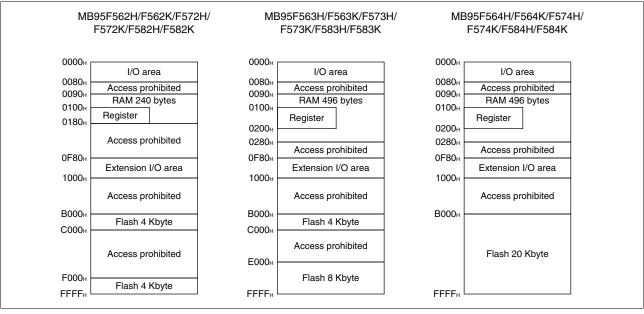


17. CPU Core

· Memory space

The memory space of the MB95560H/570H/580H is 64 Kbyte in size, and consists of an I/O area, a data area, and a program area. The memory space includes areas intended for specific purposes such as general-purpose registers and a vector table. The memory maps of the MB95560H/570H/580H are shown below.8

Memory maps





18. I/O Map (MB95560H Series)

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000в
0001н	DDR0	Port 0 direction register	R/W	0000000в
0002н	PDR1	Port 1 data register	R/W	0000000в
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н		(Disabled)	—	
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111в
0006н	PLLC	PLL control register	R/W	000Х000в
0007н	SYCC	System clock control register	R/W	XXX11011 _B
0008н	STBC	Standby control register	R/W	0000000в
0009н	RSRR	Reset source register	R/W	000XXXXX _B
000Ан	TBTC	Time-base timer control register	R/W	0000000в
000Bн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	00XX0000b
000Dн	SYCC2	System clock control register 2	R/W	ХХХХ0011в
000Е н	STBC2	Standby control register 2	R/W	0000000в
000F н				
to	_	(Disabled)	—	—
0015 н				
0016н	PDR6	Port 6 data register	R/W	0000000в
0017 н	DDR6	Port 6 direction register	R/W	0000000в
0018 н		-		
to	_	(Disabled)	_	
0027 н				
0028н	PDRF	Port F data register	R/W	0000000в
0029н	DDRF	Port F direction register	R/W	0000000в
002Aн	PDRG	Port G data register	R/W	0000000в
002Bн	DDRG	Port G direction register	R/W	0000000в
002Сн	PUL0	Port 0 pull-up register	R/W	0000000в
002Dн				
to	_	(Disabled)	_	
0032н				
0033н	PUL6	Port 6 pull-up register	R/W	0000000в
0034н		(Disabled)	—	
0035н	PULG	Port G pull-up register	R/W	0000000в
0036н	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	0000000в
0037н	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	0000000в
0038н	T11CR1	8/16-bit composite timer 11 status control register 1	R/W	0000000в
0039н	T10CR1	8/16-bit composite timer 10 status control register 1	R/W	0000000в
003Ан				
to	_	(Disabled)	_	
0048н		· · · · · · · · · · · · · · · · · · ·		



Address	Register abbreviation	Register name	R/W	Initial value
0049н	EIC10	External interrupt circuit control register ch. 2/ch. 3	R/W	0000000в
004Ан	EIC20	External interrupt circuit control register ch. 4/ch. 5	R/W	0000000в
004В н	EIC30	External interrupt circuit control register ch. 6/ch. 7	R/W	0000000в
004Сн,		(Disabled)		
004Dн			_	—
004Е н	LVDR	LVDR reset voltage selection ID register	R/W	0000000в
004F н	_	(Disabled)	_	—
0050н	SCR	LIN-UART serial control register	R/W	0000000в
0051 н	SMR	LIN-UART serial mode register	R/W	0000000в
0052н	SSR	LIN-UART serial status register	R/W	00001000в
0053н	RDR	LIN-UART receive data register	R/W	0000000в
	TDR	LIN-UART transmit data register	R/W	0000000в
0054 н	ESCR	LIN-UART extended status control register	R/W	00000100в
0055н	ECCR	LIN-UART extended communication control register	R/W	000000XXв
0056н				
to	—	(Disabled)	_	—
006Bн				
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000в
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000в
006Е н	ADDH	8/10-bit A/D converter data register (upper)	R/W	0000000в
006Fн	ADDL	8/10-bit A/D converter data register (lower)	R/W	0000000в
0070н		(Disabled)	—	
0071 н	FSR2	Flash memory status register 2	R/W	0000000в
0072н	FSR	Flash memory status register	R/W	000Х0000в
0073н	SWRE0	Flash memory sector write control register 0	R/W	0000000в
0074н	FSR3	Flash memory status register 3	R	000XXXXX _B
0075н	FSR4	Flash memory status register 4	R/W	0000000в
0076н	WREN	Wild register address compare enable register	R/W	0000000в
0077н	WROR	Wild register data test setting register	R/W	0000000в
0078 н	_	Mirror of register bank pointer (RP) and direct bank pointer (DP)	—	—
0079 н	ILR0	Interrupt level setting register 0	R/W	11111111в
007Ан	ILR1	Interrupt level setting register 1	R/W	11111111в
007В н	ILR2	Interrupt level setting register 2	R/W	11111111в
007Сн	ILR3	Interrupt level setting register 3	R/W	11111111в
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111в
007Е н	ILR5	Interrupt level setting register 5	R/W	11111111в
007F н		(Disabled)	—	—
0F80н	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (lower) ch. 0	R/W	0000000в
0F82н	WRDR0	Wild register data setting register ch. 0	R/W	0000000в





Address	Register abbreviation	Register name	R/W	Initial value
0F83н	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0000000в
0F84н	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0000000в
0F85⊦	WRDR1	Wild register data setting register ch. 1	R/W	0000000в
0F86н	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0000000в
0F87н	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0000000в
0F88⊦	WRDR2	Wild register data setting register ch. 2	R/W	0000000в
0F89н to 0F91н	_	(Disabled)	_	_
0F92н	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0000000в
0F93н	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0000000в
0F94н	T01DR	8/16-bit composite timer 01 data register	R/W	0000000в
0F95н	T00DR	8/16-bit composite timer 00 data register	R/W	0000000в
0F96н	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0000000в
0F97н	T11CR0	8/16-bit composite timer 11 status control register 0	R/W	0000000в
0F98н	T10CR0	8/16-bit composite timer 10 status control register 0	R/W	0000000в
0F99н	T11DR	8/16-bit composite timer 11 data register	R/W	0000000в
0F9Aн	T10DR	8/16-bit composite timer 10 data register	R/W	0000000в
0F9Bн	TMCR1	8/16-bit composite timer 10/11 timer mode control register	R/W	0000000в
0F9Cн to 0FBBн		(Disabled)	_	_
0FBCH	BGR1	LIN-UART baud rate generator register 1	R/W	0000000в
0FBDH	BGR0	LIN-UART baud rate generator register 0	R/W	0000000в
0FBEн to 0FC2н		(Disabled)	_	
0FC3н	AIDRL	A/D input disable register (lower)	R/W	0000000в
0FC4н to 0FE3н		(Disabled)	_	_
0FE4н	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXX _B
0FE5н	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXX _B
0FE6н		(Disabled)	—	_
0FE7н	CRTDA	Main CR clock temperature dependent adjustment register	R/W	000XXXXX _B
0FE8н	SYSC	System configuration register	R/W	11000011в
0FE9н	CMCR	Clock monitoring control register	R/W	0000000в
0FEAH	CMDR	Clock monitoring data register	R	00000000в



Address	Register abbreviation	Register name	R/W	Initial value
0FEBH	WDTH	Watchdog timer selection ID register (upper)	R	XXXXXXXXB
0FECH	WDTL	Watchdog timer selection ID register (lower)	R	XXXXXXXXB
0FEDн to 0FFFн		(Disabled)	_	_

• R/W access symbols

R/W : Readable / Writable

R : Read only

Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.

Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.



19. I/O Map (MB95570H Series)

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000в
0001н	DDR0	Port 0 direction register	R/W	0000000в
0002н	PDR1	Port 1 data register	R/W	0000000в
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н	—	(Disabled)	—	—
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111в
0006н	PLLC	PLL control register	R/W	000Х000в
0007н	SYCC	System clock control register	R/W	XXX11011 _B
0008н	STBC	Standby control register	R/W	0000000в
0009н	RSRR	Reset source register	R/W	000XXXXX _B
000Ан	TBTC	Time-base timer control register	R/W	0000000в
000Вн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	00XX0000b
000Dн	SYCC2	System clock control register 2	R/W	ХХХХ0011в
000Е н	STBC2	Standby control register 2	R/W	0000000в
000F н				
to	_	(Disabled)	_	—
0027н				
0028н	PDRF	Port F data register	R/W	0000000в
0029н	DDRF	Port F direction register	R/W	0000000в
002Ан,		(Dischlad)		
002Bн	_	(Disabled)		_
002Сн	PUL0	Port 0 pull-up register	R/W	0000000в
002Dн				
to	_	(Disabled)	_	—
0035н				
0036н	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	0000000в
0037 н	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	0000000в
0038н				
to	—	(Disabled)	_	—
0049н				
004Ан	EIC20	External interrupt circuit control register ch. 4/ch. 5	R/W	0000000в
004Вн	EIC30	External interrupt circuit control register ch. 6/ch. 7	R/W	0000000в
004Сн,		(Disabled)		
004Dн		(Disabled)		—
004Е н	LVDR	LVDR reset voltage selection ID register	R/W	0000000в
004F н		- • •		
to	_	(Disabled)	_	—
006Bн				



Address	Register abbreviation	Register name	R/W	Initial value
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000в
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000в
006Eн	ADDH	8/10-bit A/D converter data register (upper)	R/W	0000000в
006F н	ADDL	8/10-bit A/D converter data register (lower)	R/W	0000000в
0070н	—	(Disabled)	—	—
0071 н	FSR2	Flash memory status register 2	R/W	0000000в
0072н	FSR	Flash memory status register	R/W	000Х000в
0073н	SWRE0	Flash memory sector write control register 0	R/W	0000000в
0074н	FSR3	Flash memory status register 3	R	000XXXXX _B
0075н	FSR4	Flash memory status register 4	R/W	0000000в
0076н	WREN	Wild register address compare enable register	R/W	0000000в
0077н	WROR	Wild register data test setting register	R/W	0000000в
0078 н	—	Mirror of register bank pointer (RP) and direct bank pointer (DP)	_	—
0079 н	ILR0	Interrupt level setting register 0	R/W	11111111в
007Ан	ILR1	Interrupt level setting register 1	R/W	11111111в
007Вн,		(Disabled)		
007С н		(Disabled)		
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111в
007Е н	ILR5	Interrupt level setting register 5	R/W	11111111в
007F н	—	(Disabled)	—	—
0F80н	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (lower) ch. 0	R/W	0000000в
0F82н	WRDR0	Wild register data setting register ch. 0	R/W	0000000в
0F83н	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0000000в
0F84н	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0000000в
0F85н	WRDR1	Wild register data setting register ch. 1	R/W	0000000в
0F86н	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0000000в
0F87н	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0000000в
0F88н	WRDR2	Wild register data setting register ch. 2	R/W	0000000в
0F89н				
to	—	(Disabled)	—	—
0F91н				
0F92н	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0000000в
0F93н	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0000000в
0F94н	T01DR	8/16-bit composite timer 01 data register	R/W	0000000в
0F95н	T00DR	8/16-bit composite timer 00 data register	R/W	0000000в
0F96н	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0000000в
0F97н to		(Disabled)		
0FC2н				





Address	Register abbreviation	Register name	R/W	Initial value
0FC3н	AIDRL	A/D input disable register (lower)	R/W	0000000в
0FC4н to 0FE3н	_	(Disabled)	_	_
0FE4H	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXX _B
0FE5н	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXX _B
0FE6н	_	(Disabled)	—	—
0FE7н	CRTDA	Main CR clock temperature dependent adjustment register	R/W	000XXXXX _B
0FE8н	SYSC	System configuration register	R/W	11000011в
0FE9н	CMCR	Clock monitoring control register	R/W	0000000в
0FEAH	CMDR	Clock monitoring data register	R	0000000в
0FEBH	WDTH	Watchdog timer selection ID register (upper)	R	XXXXXXXXB
0FECH	WDTL	Watchdog timer selection ID register (lower)	R	XXXXXXXXB
0FEDн to 0FFFн		(Disabled)	_	_

• R/W access symbols

- R/W : Readable / Writable
- R : Read only

• Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.

Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.



20. I/O Map (MB95580H Series)

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000в
0001н	DDR0	Port 0 direction register	R/W	0000000в
0002н	PDR1	Port 1 data register	R/W	0000000в
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н	—	(Disabled)	—	—
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111в
0006н	PLLC	PLL control register	R/W	000Х000в
0007н	SYCC	System clock control register	R/W	XXX11011 _B
0008н	STBC	Standby control register	R/W	0000000в
0009н	RSRR	Reset source register	R/W	000XXXXXB
000Ан	TBTC	Time-base timer control register	R/W	0000000в
000Вн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	00XX0000 _B
000Dн	SYCC2	System clock control register 2	R/W	XXXX0011 _B
000Е н	STBC2	Standby control register 2	R/W	0000000в
000Fн				
to	_	(Disabled)	—	
0027 н				
0028н	PDRF	Port F data register	R/W	0000000в
0029н	DDRF	Port F direction register	R/W	0000000в
002Ан	PDRG	Port G data register	R/W	0000000в
002Вн	DDRG	Port G direction register	R/W	0000000в
002Сн	PUL0	Port 0 pull-up register	R/W	0000000в
002Dн				
to	—	(Disabled)	—	
0034н				
0035н	PULG	Port G pull-up register	R/W	0000000в
0036н	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	0000000в
0037н	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	0000000в
0038н				
to	—	(Disabled)	—	
0048 н				
0049н	EIC10	External interrupt circuit control register ch. 2/ch. 3	R/W	0000000в
004Ан	EIC20	External interrupt circuit control register ch. 4/ch. 5	R/W	0000000в
004В н	EIC30	External interrupt circuit control register ch. 6/ch. 7	R/W	0000000в
004Сн,		(Dischled)		
004Dн	-	(Disabled)		
004Е н	LVDR	LVDR reset voltage selection ID register	R/W	0000000в
004F н	—	(Disabled)	—	



Address	Register abbreviation	Register name	R/W	Initial value
0050н	SCR	LIN-UART serial control register	R/W	0000000в
0051 н	SMR	LIN-UART serial mode register	R/W	0000000в
0052н	SSR	LIN-UART serial status register	R/W	00001000в
0053н	RDR	LIN-UART receive data register	R/W	0000000в
	TDR	LIN-UART transmit data register	R/W	0000000в
0054н	ESCR	LIN-UART extended status control register	R/W	00000100в
0055н	ECCR	LIN-UART extended communication control register	R/W	000000XXB
0056н				
to	—	(Disabled)	—	—
006В н				
006С н	ADC1	8/10-bit A/D converter control register 1	R/W	0000000в
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000в
006Е н	ADDH	8/10-bit A/D converter data register (upper)	R/W	0000000в
006F н	ADDL	8/10-bit A/D converter data register (lower)	R/W	0000000в
0070н	_	(Disabled)	—	
0071 н	FSR2	Flash memory status register 2	R/W	0000000в
0072н	FSR	Flash memory status register	R/W	000Х000в
0073н	SWRE0	Flash memory sector write control register 0		0000000в
0074н	FSR3	Flash memory status register 3		000XXXXXB
0075н	FSR4	Flash memory status register 4	R/W	0000000в
0076н	WREN	Wild register address compare enable register	R/W	0000000в
0077 н	WROR	Wild register data test setting register	R/W	0000000в
0078 н	_	Mirror of register bank pointer (RP) and direct bank pointer (DP)	_	_
0079 н	ILR0	Interrupt level setting register 0	R/W	11111111в
007Ан	ILR1	Interrupt level setting register 1	R/W	11111111в
007В н	ILR2	Interrupt level setting register 2	R/W	11111111в
007Сн		(Disabled)		_
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111в
007Е н	ILR5	Interrupt level setting register 5	R/W	11111111в
007F н	_	(Disabled)	—	
0F80н	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (lower) ch. 0	R/W	0000000в
0F82н	WRDR0	Wild register data setting register ch. 0	R/W	0000000в
0F83н	WRARH1	Wild register address setting register (upper) ch. 1		0000000в
0F84н	WRARL1	Wild register address setting register (lower) ch. 1		0000000в
0F85н	WRDR1	Wild register data setting register ch. 1		0000000в
0F86н	WRARH2	Wild register address setting register (upper) ch. 2		0000000в
0F87н	WRARL2	Wild register address setting register (lower) ch. 2	R/W R/W	0000000в
0F88H	WRDR2	Wild register data setting register ch. 2	R/W	0000000в



Address	Register abbreviation	Register name	R/W	Initial value
0F89н				
to	—	(Disabled)		—
0F91н				
0F92н	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0000000в
0F93н	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0000000в
0F94н	T01DR	8/16-bit composite timer 01 data register	R/W	0000000в
0F95н	T00DR	8/16-bit composite timer 00 data register	R/W	0000000в
0F96н	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0000000в
0F97н				
to	—	(Disabled)	—	—
0FBBн				
0FBCH	BGR1	LIN-UART baud rate generator register 1	R/W	0000000в
0FBDH	BGR0	LIN-UART baud rate generator register 0	R/W	0000000в
0FBEH				
to	—	(Disabled)		—
0FC2H				
0FC3н	AIDRL	A/D input disable register (lower)	R/W	0000000в
0FC4н				
to	—	(Disabled)		—
0FE3H				
0FE4H	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXXB
0FE5н	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXXB
0FE6н	—	(Disabled)	_	—
0FE7н	CRTDA	Main CR clock temperature dependent adjustment register	R/W	000XXXXXB
0FE8н	SYSC	System configuration register	R/W	11000011в
0FE9н	CMCR	Clock monitoring control register	R/W	0000000в
0FEAн	CMDR	Clock monitoring data register	R	0000000в
0FEBH	WDTH	Watchdog timer selection ID register (upper)	R	XXXXXXXXB
0FECH	WDTL	Watchdog timer selection ID register (lower)	R	XXXXXXXXB
0FEDH				
to	—	(Disabled)	—	—
0FFFH				

• R/W access symbols

- R/W : Readable / Writable
- R : Read only

Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.

Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.



21. Interrupt Source Table (MB95560H Series)

		Vector tab	le address		Priority order of	
Interrupt source	Interrupt request number			Bit name of interrupt level setting register	interruptsources of the same level (occurring simultaneously)	
External interrupt ch. 4	IRQ00	FFFA H	FFFB H	L00 [1:0]	High	
External interrupt ch. 5	IRQ01	FFF8⊦	FFF9⊦	L01 [1:0]	A	
External interrupt ch. 2	IRQ02	FFF6H	FFF7H	L02 [1:0]		
External interrupt ch. 6		ГГГОН	FFF/H	L02 [1.0]		
External interrupt ch. 3	IRQ03	FFF4 _H	FFF5⊦	L03 [1:0]		
External interrupt ch. 7		FFF4H	гггэн	LU3 [1.0]		
_	IRQ04	FFF2н	FFF3н	L04 [1:0]		
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0H	FFF1 _H	L05 [1:0]		
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEEH	FFEFH	L06 [1:0]		
LIN-UART (reception)	IRQ07	FFECH	FFEDH	L07 [1:0]		
LIN-UART (transmission)	IRQ08	FFEAH	FFEBH	L08 [1:0]		
—	IRQ09	FFE8H	FFE9H	L09 [1:0]		
—	IRQ10	FFE6H	FFE7H	L10 [1:0]		
_	IRQ11	FFE4H	FFE5H	L11 [1:0]		
—	IRQ12	FFE2H	FFE3H	L12 [1:0]		
—	IRQ13	FFE0H	FFE1н	L13 [1:0]		
8/16-bit composite timer ch. 1 (upper)	IRQ14	FFDEH	FFDFH	L14 [1:0]		
_	IRQ15	FFDC H	FFDD H	L15 [1:0]		
—	IRQ16	FFDAH	FFDB H	L16 [1:0]		
_	IRQ17	FFD8н	FFD9н	L17 [1:0]		
8/10-bit A/D converter	IRQ18	FFD6н	FFD7н	L18 [1:0]		
Time-base timer	IRQ19	FFD4н	FFD5н	L19 [1:0]		
Watch prescaler	IRQ20	FFD2н	FFD3н	L20 [1:0]		
—	IRQ21	FFD0н	FFD1н	L21 [1:0]		
8/16-bit composite timer ch. 1 (lower)	IRQ22	FFCEH	FFCFH	L22 [1:0]		
Flash memory	IRQ23	FFCCH	FFCDH	L23 [1:0]	Low	



22. Interrupt Source Table (MB95570H Series)

	• • • •	Vector tab	le address		Priority order of interruptsources of the same level (occurring simultaneously)	
Interrupt source	Interrupt request number	Upper	Lower	Bit name of interrupt level setting register		
External interrupt ch. 4	IRQ00	FFFA H	FFFB H	L00 [1:0]	High	
—	IRQ01	FFF8H	FFF9н	L01 [1:0]	▲	
 External interrupt ch. 6	IRQ02	FFF6 _H	FFF7⊦	L02 [1:0]		
	IRQ03	FFF4⊦	FFF5⊦	L03 [1:0]		
	IRQ04	FFF2H	FFF3H	L04 [1:0]		
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0H	FFF1 _H	L05 [1:0]		
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEEH	FFEFн	L06 [1:0]		
	IRQ07	FFECH	FFEDH	L07 [1:0]		
—	IRQ08	FFEA H	FFEBH	L08 [1:0]		
—	IRQ09	FFE8H	FFE9H	L09 [1:0]		
—	IRQ10	FFE6H	FFE7H	L10 [1:0]		
—	IRQ11	FFE4H	FFE5⊦	L11 [1:0]		
—	IRQ12	FFE2H	FFE3H	L12 [1:0]		
—	IRQ13	FFE0H	FFE1н	L13 [1:0]		
	IRQ14	FFDEH	FFDFH	L14 [1:0]		
	IRQ15	FFDC H	FFDD H	L15 [1:0]		
—	IRQ16	FFDAH	FFDB H	L16 [1:0]		
	IRQ17	FFD8H	FFD9н	L17 [1:0]		
8/10-bit A/D converter	IRQ18	FFD6н	FFD7н	L18 [1:0]		
Time-base timer	IRQ19	FFD4н	FFD5н	L19 [1:0]		
Watch prescaler	IRQ20	FFD2H	FFD3н	L20 [1:0]		
_	IRQ21	FFD0н	FFD1н	L21 [1:0]		
	IRQ22	FFCEH	FFCFH	L22 [1:0]	▼	
Flash memory	IRQ23	FFCC H	FFCDH	L23 [1:0]	Low	



23. Interrupt Source Table (MB95580H Series)

		Vector tab	le address		Priority order of interruptsources of the same level (occurring simultaneously)	
Interrupt source	Interrupt request number	Upper	Lower	Bit name of interrupt level setting register		
External interrupt ch. 4	IRQ00	FFFA H	FFFB H	L00 [1:0]	High	
External interrupt ch. 5	IRQ01	FFF8н	FFF9н	L01 [1:0]	▲	
External interrupt ch. 2	IRQ02	FFF6H	FFF7H	L02 [1:0]		
External interrupt ch. 6		ГГГОН	FFF/H	LUZ [1.0]		
External interrupt ch. 3	IRQ03	FFF4 _H	FFF5H	1 03 [1.0]		
External interrupt ch. 7		ГГГ4 H	гггэн	L03 [1:0]		
—	IRQ04	FFF2H	FFF3н	L04 [1:0]		
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0H	FFF1 _H	L05 [1:0]		
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEEH	FFEFH	L06 [1:0]		
LIN-UART (reception)	IRQ07	FFECH	FFEDH	L07 [1:0]		
LIN-UART (transmission)	IRQ08	FFEAH	FFEBH	L08 [1:0]		
—	IRQ09	FFE8H	FFE9H	L09 [1:0]		
—	IRQ10	FFE6H	FFE7H	L10 [1:0]		
	IRQ11	FFE4H	FFE5H	L11 [1:0]		
	IRQ12	FFE2H	FFE3H	L12 [1:0]		
	IRQ13	FFE0H	FFE1н	L13 [1:0]		
	IRQ14	FFDEH	FFDFH	L14 [1:0]		
	IRQ15	FFDC H	FFDDH	L15 [1:0]		
_	IRQ16	FFDAH	FFDB H	L16 [1:0]		
	IRQ17	FFD8н	FFD9н	L17 [1:0]		
8/10-bit A/D converter	IRQ18	FFD6н	FFD7н	L18 [1:0]		
Time-base timer	IRQ19	FFD4н	FFD5H	L19 [1:0]		
Watch prescaler	IRQ20	FFD2H	FFD3н	L20 [1:0]		
	IRQ21	FFD0н	FFD1н	L21 [1:0]		
—	IRQ22	FFCEH	FFCF H	L22 [1:0]	▼	
Flash memory	IRQ23	FFCC H	FFCD H	L23 [1:0]	Low	



24. Electrical Characteristics

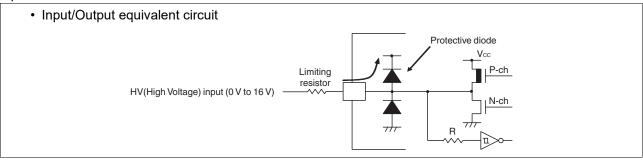
24.1 Absolute Maximum Ratings

Deremeter	Symbol	Rating		Unit	Remarks		
Parameter	Symbol	Min	Max	Unit	Remarks		
Power supply voltage*1	Vcc	V ss - 0.3	Vss + 6	V			
Input voltage*1	Vi	$V_{\text{SS}}-0.3$	Vss + 6	V	*2		
Output voltage*1	Vo	$V_{\text{SS}}-0.3$	Vss + 6	V	*2		
Maximum clamp current		-2	+2	mA	Applicable to specific pins ^{*3}		
Total maximum clamp current	Σ	_	20	mA	Applicable to specific pins ^{*3}		
"L" level maximum output current	loι	_	15	mA			
"L" level average current	Iolav1	_	4	mA	Other than P00 to P03, P05 to P07, P62 to P64 ^{*4} Average output current= operating current × operating ratio (1 pin)		
	Iolav2		12		P00 to P03, P05 to P07, P62 to P64 ^{*4} Average output current= operating current × operating ratio (1 pin)		
"L" level total maximum output current	ΣΙοι	_	100	mA			
"L" level total average output current	Σ Iolav	_	50	mA	Total average output current= operating current × operating ratio (Total number of pins)		
"H" level maximum output current	Іон	_	-15	mA			
"H" level average current	Іонаv1		-4	mA	Other than P00 to P03, P05 to P07, P62 to P64 ^{*4} Average output current= operating current × operating ratio (1 pin)		
current	Іонаv2		-8		P00 to P03, P05 to P07, P62 to P64 ^{*4} Average output current= operating current × operating ratio (1 pin)		
"H" level total maximum output current	ΣІон	_	-100	mA			
"H" level total average output current	ΣΙοήαν	_	-50	mA	Total average output current= operating current × operating ratio (Total number of pins)		
Power consumption	P₫	—	320	mW			
Operating temperature	TA	-40	+85	°C			
Storage temperature	Tstg	-55	+150	°C			

*1: These parameters are based on the condition that Vss is 0.0 V.



- *2: V_I and V₀ must not exceed V_{CC} + 0.3 V. V_I must not exceed the rated voltage. However, if the maximum current to/ from an input is limited by means of an external component, the I_{CLAMP} rating is used instead of the V_I rating.
- *3: Applicable to the following pins: P00 to P07, P62 to P64, PF0, PF1, PG1, PG2 (P00, and P62 to P64 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K. P01, P02, P03, P07, PF0. PF1, PG1, and PG2 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/F582H/F582K/F583H/F583K/F584H/F584K.)
 - Use under recommended operating conditions.
 - Use with DC voltage (current).
 - The HV (High Voltage) signal is an input signal exceeding the Vcc voltage. Always connect a limiting resistor between the HV (High Voltage) signal and the microcontroller before applying the HV (High Voltage) signal.
 - The value of the limiting resistor should be set to a value at which the current to be input to the microcontroller pin when the HV (High Voltage) signal is input is below the standard value, irrespective of whether the current is transient current or stationary current.
 - When the microcontroller drive current is low, such as in low power consumption modes, the HV (High Voltage) input potential may pass through the protective diode to increase the potential of the Vcc pin, affecting other devices.
 - If the HV (High Voltage) signal is input when the microcontroller power supply is off (not fixed at 0 V), since power is supplied from the pins, incomplete operations may be executed.
 - If the HV (High Voltage) input is input after power-on, since power is supplied from the pins, the voltage of power supply may not be sufficient to enable a power-on reset.
 - Do not leave the HV (High Voltage) input pin unconnected.
 - Example of a recommended circuit:



*4: P62 and P63 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K.

WARNING: Semiconductor devices may be permanently damaged by application of stress (including, without limitation, voltage, current or temperature) in excess of absolute maximum ratings. Do not exceed any of these ratings.



24.2 Recommended Operating Conditions

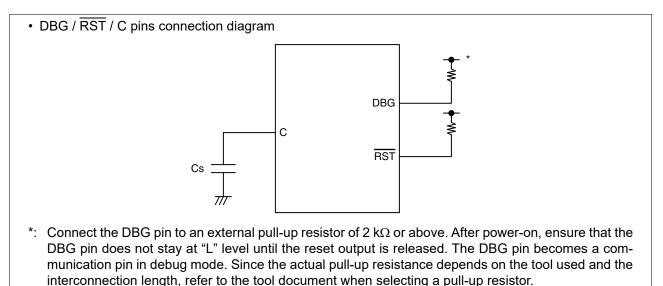
 $(V_{SS} = 0.0 V)$

Parameter	Symbol	Value		Unit	Remarks				
i arameter	Symbol	Min	Max	onit	Nemains				
		2.4* ^{1, *2}	5.5* ¹		In normal operation	Other than on-chip debug			
Power supply	Vcc	2.3	5.5	v	Hold condition in stop mode	mode			
voltage	VCC	2.9	5.5	v	In normal operation	On-chip debug mode			
		2.3	5.5		Hold condition in stop mode	On-chip debug mode			
Decoupling capacitor	Cs	0.022	1	μF	*3				
Operating	TA	-40	+85	0°	Other than on-chip debug mode				
temperature	IA	+5	+35	C	On-chip debug mode				

*1: The value varies depending on the operating frequency, the machine clock and the analog guaranteed range.

*2: The minimum power supply voltage becomes 2.88 V when a product with the low-voltage detection reset is used.

*3: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the Vcc pin must have a capacitance equal to or larger than the capacitance of Cs. For the connection to a decoupling capacitor Cs, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and Cs and the distance between Cs and the Vss pin when designing the layout of a printed circuit board.



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the

semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.

Any use of semiconductor devices will be under their recommended operating condition. Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.

No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.



24.3 DC Characteristics

(Vcc = 5.0 V \pm 10%, Vss = 0.0 V, TA = –40 °C to +85 °C)

Doromotor	Sympol	Din nomo	Condition		Value		l l mit	Remarks	
Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit		
	Vін	P04	—	0.7 Vcc	—	Vcc + 0.3	V	Hysteresis input	
"H" level input voltage	Vihs	P00 ^{*3} to P03 ^{*4} , P05 to P07 ^{*4} , P12, P62 to P64 ^{*3} , PF0 ^{*4} , PF1 ^{*4} , PG1 ^{*4} , PG2 ^{*4}	_	0.8 Vcc	_	Vcc + 0.3	V	Hysteresis input	
	VIHM	PF2	—	0.8 Vcc		Vcc + 0.3	V	Hysteresis input	
	VIL	P04	—	V ss - 0.3	_	0.3 Vcc	V	Hysteresis input	
"L" level input voltage	Vils	P00 ^{*3} to P03 ^{*4} , P05 to P07 ^{*4} , P12, P62 to P64 ^{*3} , PF0 ^{*4} , PF1 ^{*4} , PG1 ^{*4} , PG2 ^{*4}	_	Vss – 0.3		0.2 Vcc	V	Hysteresis input	
	VILM	PF2	—	V ss - 0.3		0.2 Vcc	V	Hysteresis input	
Open-drain output application voltage	VD	P12, PF2	_	Vss – 0.3	_	Vss + 5.5	v		
"H" level	Voh1	P04, PF0* ⁴ , PF1* ⁴ , PG1* ⁴ , PG2	Iон = –4 mA	Vcc - 0.5			V		
output voltage	Vон2	P00* ³ to P03* ⁴ , P05 to P07* ⁴ , P62 to P64* ³	Iон = –8 mA	Vcc - 0.5	_		V		
"L" level	Vol1	P04, P12, PF0 to PF2*4, PG1*4, PG2*4	lo∟ = 4 mA	_		0.4	V		
output voltage		P00* ³ to P03* ⁴ , P05 to P07* ⁴ , P62 to P64* ³	lo∟ = 12 mA	_		0.4	V		
Input leak current (Hi-Z output leak current)	lu	All input pins	0.0 V < Vı < Vcc	-5		+5	μA	When the internal pull-up resistor is disabled	
Internal pull-up resistor	Rpull	P00* ³ to P07* ⁴ , P62 to P64* ³ , PG1* ⁴ , PG2* ⁴	Vi = 0 V	25	50	100	kΩ	When the internal pull-up resistor is enabled	
Input capacitance	CIN	Other than Vcc and Vss	f = 1 MHz	_	5	15	pF		



Demotes	O. make al	Pin name			Value		11	Remarks
Parameter	Symbol		Condition	Min	Typ*1	Max*2	Unit	Remarks
			Fсн = 32 MHz	_	3.5	4.4	mA	Except during Flash memory programming and erasing
	lcc		F _{MP} = 16 MHz Main clock mode (divided by 2)	_	7.4	9.8	mA	During Flash memory programming and erasing
				_	5.1	6.4	mA	At A/D conversion
	lccs	Vcc (External clock	F _{CH} = 32 MHz F _{MP} = 16 MHz Main sleep mode (divided by 2)	_	1.2	1.5	mA	
	lcc∟	operation)	$F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 16 \text{ kHz}$ Subclock mode (divided by 2) $T_A = +25 \text{ °C}$	_	65	71	μA	
Power supply current*5	Iccls*6		F_{CL} = 32 kHz F_{MPL} = 16 kHz Subsleep mode (divided by 2) T_A = +25 °C		5.4	7	μA	In deep standby mode
	Iсст* ⁶		$F_{CL} = 32 \text{ kHz}$ Watch mode $T_A = +25 \text{ °C}$	_	4.8	6.9	μA	In deep standby mode
	ICCMCR	Vcc	F _{CRH} = 4 MHz F _{MP} = 4 MHz Main CR clock mode	_	1.1	1.4	mA	
	Iccscr	VCC	Sub-CR clock mode (divided by 2) $T_A = +25 \text{ °C}$	_	58	64	μA	
	Ісстѕ		F _{CH} = 32 MHz Time-base timer mode T _A = +25 °C	_	290	340	μA	In deep standby mode
	Іссн	Vcc (External clock operation)	Main stop mode (single external clock product)/ Substop mode (dual external clock product) T _A = +25 °C		4.1	6.5	μΑ	In deep standby mode

(Vcc = 5.0 V \pm 10%, Vss = 0.0 V, T_A = -40 °C to +85 °C)



			()		Value	70, 100			
Parameter	Symbol	Pin name	Condition	Min	Typ*1	Max*2	Unit	Remarks	
	Ilvd		Current consumption for the low-voltage detection circuit	_	3.6	6.6	μA		
	ICRH	Current consumption for the main CR oscillator	—	220	280	μA			
Power supply current* ⁵	Icrl	Vcc	Current consumption for the sub-CR oscillator oscillating at 100 kHz		5.1	9.3	μA		
	Instby		Current consumption difference between normal standby mode and deep standby mode $T_A = +25 \ ^{\circ}C$	_	20	30	μΑ		

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$

*1: Vcc = 5.0 V, T_A = + 25 °C

*2: Vcc = 5.5 V, T_A = + 85 °C (unless otherwise specified)

*3: P00, P62, P63 and P64 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K.

- *4: P01, P02, P03, P07, PF0, PF1, PG1 and PG2 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/ F582H/F582K/F583H/F583K/F584H/F584K.
- *5: The power supply current is determined by the external clock. When the low-voltage detection option is selected, the power-supply current will be the sum of adding the current consumption of the low-voltage detection circuit (ILVD) to one of the value from Icc to IccH. In addition, when both the low-voltage detection option and the CR oscillator are selected, the power supply current will be the sum of adding up the current consumption of the low-voltage detection circuit, the current consumption of the CR oscillators (ICRH, ICRL) and a specified value. In on-chip debug mode, the CR oscillator (ICRH) and the low-voltage detection circuit are always enabled, and current consumption therefore increases accordingly.
 - See "24.4 AC Characteristics: Clock Timing" for FCH and FCL.
 - See "24.4 AC Characteristics: Source Clock / Machine Clock" for F_{MP} and F_{MPL} .
- *6: In sub-CR clock mode, the power supply current value is the sum of adding ICRL to ICCLS or ICCT. In addition, when the sub-CR clock mode is selected with FMPL being 50 kHz, the current consumption increases accordingly.



24.4 AC Characteristics

24.4.1 Clock Timing

(Vcc = 2.4 V to 5.5 V, Vss = 0.0 V, T_A = -40 °C to +85 °C)

		. .	a		Value			
Parameter	Symbol	Pin name	Condition	Min	Тур	Мах	Unit	Remarks
	Fсн	X0, X1	_	1	—	16.25	MHz	When the main oscillation circuit is used
	FCH	X0	X1: open	1	—	12		When the main external clock
		X0, X1	*	1	—	32.5	MHz	is used
				3.92	4	4.08	MHz	Operating conditions • The main CR clock is used. • $0 \ ^{\circ}C \le T_{A} \le +70 \ ^{\circ}C$
	Fcrh	_	_	3.8	4	4.2	MHz	$\begin{array}{l} \text{Operating conditions}\\ \bullet \ \ \text{The main CR clock is used.}\\ \bullet \ \ -40\ \ ^{\circ}\text{C} \leq T_{\text{A}} < 0\ \ ^{\circ}\text{C},\\ +70\ \ ^{\circ}\text{C} < T_{\text{A}} \leq +85\ \ ^{\circ}\text{C} \end{array}$
				7.84	8	8.16	MHz	Operating conditions • PLL multiplication rate: 2 • $0 \ ^{\circ}C \le T_A \le +70 \ ^{\circ}C$
				7.6	8	8.4	MHz	$\begin{array}{l} \text{Operating conditions}\\ \bullet \ \ \text{PLL multiplication rate: 2}\\ \bullet \ \ -40\ \ ^{\circ}\text{C} \leq T_{\text{A}} < 0\ \ ^{\circ}\text{C},\\ +70\ \ ^{\circ}\text{C} < T_{\text{A}} \leq +85\ \ ^{\circ}\text{C} \end{array}$
Clock frequency		_		9.8	10	10.2	MHz	$\begin{array}{l} \mbox{Operating conditions}\\ \bullet \ \mbox{PLL multiplication rate: } 2.5\\ \bullet \ \ 0 \ \ \ \ C \le T_A \le +70 \ \ \ \ \ C \end{array}$
	-			9.5	10	10.5	MHz	$\begin{array}{l} \mbox{Operating conditions}\\ \bullet \ \mbox{PLL multiplication rate: 2.5}\\ \bullet \ \ -40\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ $
	FMCRPLL			11.76	12	12.24	MHz	Operating conditions • PLL multiplication rate: 3 • 0 °C ≤ T _A ≤ +70 °C
				11.4	12	12.6	MHz	$\begin{array}{l} \text{Operating conditions}\\ \bullet \ \text{PLL multiplication rate: 3}\\ \bullet \ -40 \ ^\circ\text{C} \leq T_\text{A} < 0 \ ^\circ\text{C},\\ +70 \ ^\circ\text{C} < T_\text{A} \leq +85 \ ^\circ\text{C} \end{array}$
				15.68	16	16.32		Operating conditions • PLL multiplication rate: 4 • 0 °C ≤ T _A ≤ +70 °C
				15.2	16	16.8	MHz	Operating conditions • PLL multiplication rate: 4 • $-40 ^{\circ}\text{C} \leq T_{\text{A}} < 0 ^{\circ}\text{C},$ $+70 ^{\circ}\text{C} < T_{\text{A}} \leq +85 ^{\circ}\text{C}$
	F - :				32.768		kHz	When the suboscillation circuit is used
	Fc∟	X0A, X1A	_	_	32.768	_	kHz	When the sub-external clock is used
	FCRL	_	_	50	100	150	kHz	When the sub-CR clock is used

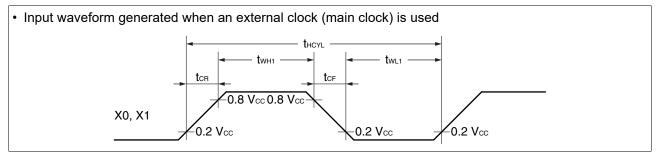


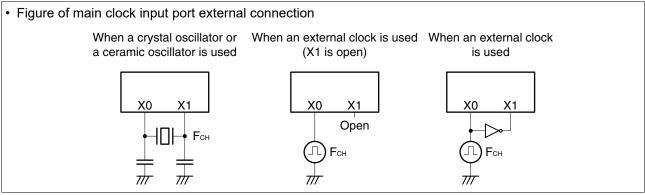


Parameter	Symbol	Din namo	Condition		Value		Unit	Remarks
Falameter	Symbol		Condition	Min	Тур	Max	Unit	Reinarks
	t	X0, X1	_	61.5	_	1000	ns	When the main oscillation circuit is used
Clock cycle time	t HCYL	X0	X1: open	83.4	—	1000	ns	When an external clock is
		X0, X1	*	30.8	—	1000	ns	used
	t LCYL	X0A, X1A	—	_	30.5	—	μs	When the subclock is used
	twн1,	X0	X1: open	33.4	—	—	ns	When an external clock is
nput clock twL1	t w∟1	X0, X1	*	12.4	—	—	ns	used, the duty ratio should
pulse width	twн2, tw∟2	X0A	_	_	15.2	_	μs	range between 40% and 60%.
Input clock	tcr,	X0, X0A	X1: open	_	—	5	ns	When an external clock is
rising time and falling time	tcr, tcr	X0, X1, X0A, X1A	*	_	_	5	ns	used
CR oscillation	t crhwk	_	_	_	_	50	μs	When the main CR clock is used
start time	t crlwk					30	μs	When the sub-CR clock is used

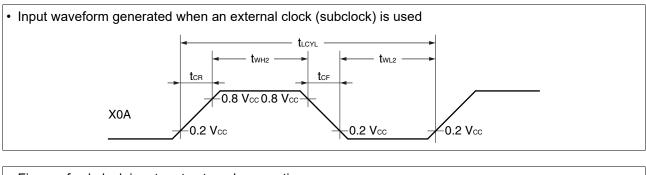
(Vcc = 2.4 V to 5.5 V, Vss = 0.0 V, T_A = -40 °C to +85 °C)

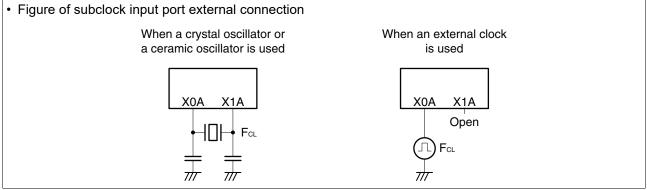
*: The external clock signal is input to X0 and the inverted external clock signal to X1.













24.4.2 Source Clock / Machine Clock

	V 00V/T 40	
10000 = 5000 + 1000	$V_{SS} = 0.0 V, T_{A} = -40$	$1 \pm 10 \pm 85$
$1000 = 0.0 v \pm 1000$	$v_{33} = 0.0 v_1 h_1 = -10$	

D (Pin		Value	-		
Parameter	Symbol	name	Min	Тур	Мах	Unit	Remarks
				21			When the main external clock is used
			61.5	—	2000	ns	Min: Fсн = 32.5 MHz, divided by 2
							Max: Fсн = 1 MHz, divided by 2
							When the main CR clock is used
Source clock	1		62.5	—	1000	ns	Min: FCRH = 4 MHz, multiplied by 4
cycle time*1	t sclk	_					Max: FCRH = 4 MHz, divided by 4
				64			When the suboscillation clock is used
			_	61	_	μs	Fc∟ = 32.768 kHz, divided by 2
							When the sub-CR clock is used
				20		μs	F _{CRL} = 100 kHz, divided by 2
			0.5	—	16.25	MHz	When the main oscillation clock is used
	Fsp			4	_	MHz	When the main CR clock is used
Source clock			_	16.384	_	kHz	When the suboscillation clock is used
frequency	FSPL			50			When the sub-CR clock is used
				50		kHz	F _{CRL} = 100 kHz, divided by 2
							When the main oscillation clock is used
			61.5	—	32000	ns	Min: Fs₂ = 16.25 MHz, no division
							Max: Fsp = 0.5 MHz, divided by 16
Machine clock							When the main CR clock is used
cycle time*2			250	—	1000	ns	Min: Fs₂ = 4 MHz, no division
(minimum							Max: Fsp = 4 MHz, divided by 4
instruction	t MCLK						When the suboscillation clock is used
execution			61	—	976.5	μs	Min: Fsp∟ = 16.384 kHz, no division
time)						-	Max: FspL = 16.384 kHz, divided by 16
							When the sub-CR clock is used
			20	—	320	μs	Min: Fsp∟ = 50 kHz, no division
						-	Max: Fsp∟ = 50 kHz, divided by 16
	Fмp		0.031	—	16.25	MHz	When the main oscillation clock is used
Machine clock	FMP		0.25	—	16	MHz	When the main CR clock is used
			1.024	—	16.384	kHz	When the suboscillation clock is used
frequency	FMPL		2 105		50		When the sub-CR clock is used
			3.125	_	50	kHz	F _{CRL} = 100 kHz

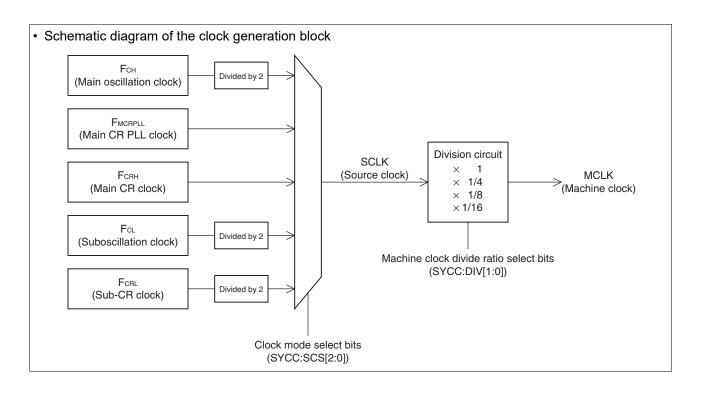
*1: This is the clock before it is divided according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). This source clock is divided to become a machine clock according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). In addition, a source clock can be selected from the following.

- Main clock divided by 2
- Main CR clock
- PLL multiplication of main CR clock (Select a multiplication rate from 2, 2.5, 3 and 4.)
- Subclock divided by 2
- Sub-CR clock divided by 2

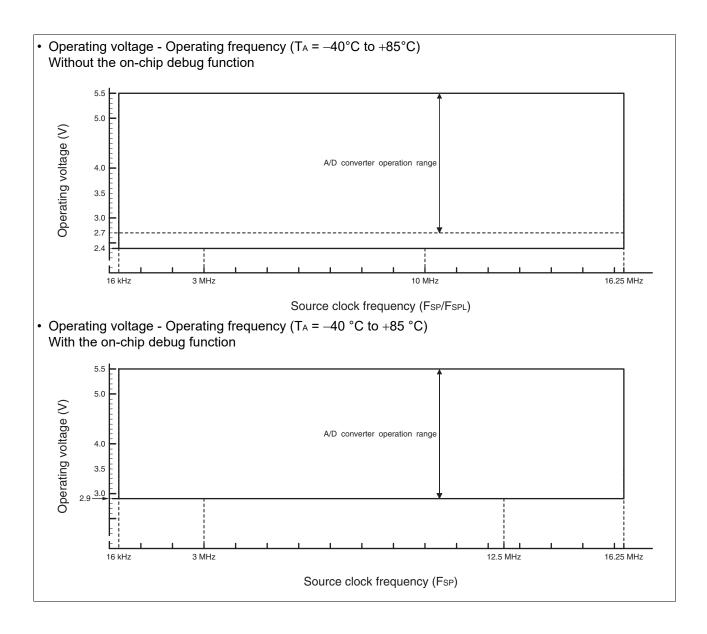
*2: This is the operating clock of the microcontroller. A machine clock can be selected from the following.

- Source clock (no division)
- Source clock divided by 4
- Source clock divided by 8
- Source clock divided by 16









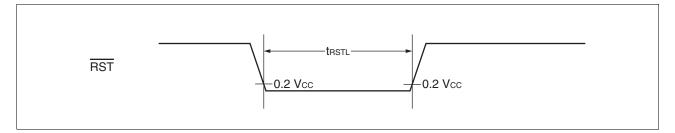


24.4.3 External Reset

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to} +85 \text{ }^{\circ}\text{C})$

Parameter	Symbol	Value		Unit	Remarks		
Falameter	Symbol	Min	Мах	Unit	ixellial K3		
RST "L" level pulse width	t rstl	2 tmclk*1	_	ns	In normal operation		

*1: See "Source Clock / Machine Clock" for tmclk.

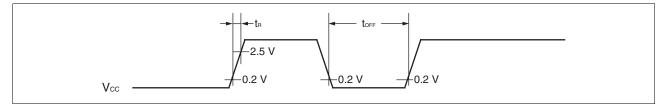




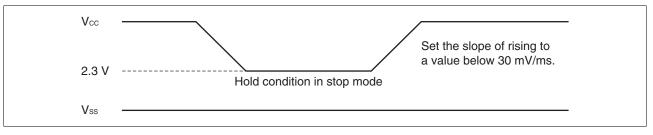
24.4.4 Power-on Reset

 $(V_{SS} = 0.0 \text{ V}, T_A = -40 \text{ °C to } +85 \text{ °C})$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks
Falameter	Symbol	Condition	Min	Мах	Unit	Remarks
Power supply rising time	tR	—	—	50	ms	
Power supply cutoff time	toff		1	—	ms	Wait time until power-on



Note: A sudden change of power supply voltage may activate the power-on reset function. When changing the power supply voltage during the operation, set the slope of rising to a value below within 30 mV/ms as shown below.



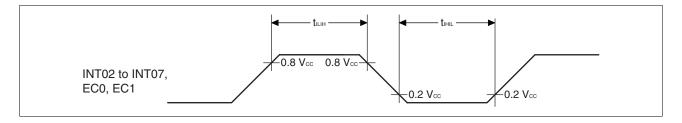
24.4.5 Peripheral Input Timing

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ V}_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$

Parameter	Symbol	Pin name	Value Min Max 2 t _{MCLK} *4 —	Unit	
Farameter	Symbol	Fill liame	Min		Unit
Peripheral input "H" pulse width	tı∟ıн	INT02 to INT07*1,*2, EC0*1, EC1*3	2 t MCLK*4	—	ns
Peripheral input "L" pulse width	tını∟		2 t MCLK*4		ns

*1: INT04, INT06 and EC0 are available on all products.

- *2: INT02, INT03, INT05 and INT07 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/F582H/ F582K/F583H/F583K/F584H/F584K.
- *3: EC1 is only available on MB95F562H/F562K/F563H/F563K/F564H/F564K.
- *4: See "Source Clock / Machine Clock" for tmclk.





24.4.6 LIN-UART Timing (only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/F582H/F582K/F583H/F583K/F584H/ F584K)

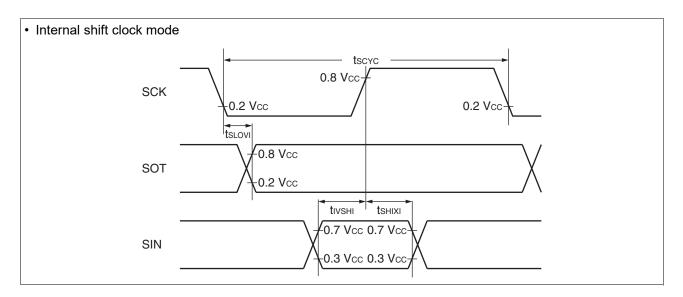
Sampling is executed at the rising edge of the sampling clock^{*1}, and serial clock delay is disabled^{*2}. (ESCR register: SCES bit = 0, ECCR register: SCDE bit = 0)

	- 5 -		$V_{cc} = 5.0 V \pm 10\%, AV_{cc}$	ss = Vss = 0.0 '	V, T _A = -40 °C	to +8
Parameter	Symbol	Pin name	Condition	Va	Unit	
Falanielei	Symbol	Finname	Condition	Min	Max	Unit
Serial clock cycle time	t scyc	SCK		5 tмськ* ³	—	ns
SCK $\downarrow \rightarrow$ SOT delay time	tslovi	SCK, SOT	Internal clock operation output pin:	-50	+50	ns
Valid SIN $ ightarrow$ SCK \uparrow	tıvshi	SCK, SIN	$C_{L} = 80 \text{ pF} + 1 \text{ TTL}$	$t_{\text{MCLK}^{*3}} + 80$	_	ns
SCK $\uparrow \rightarrow$ valid SIN hold time	tshixi	SCK, SIN		0	—	ns
Serial clock "L" pulse width	t _{SLSH}	SCK		$3 \ t_{\text{MCLK}^{\star 3}} - t_{\text{R}}$	—	ns
Serial clock "H" pulse width	t shsl	SCK		t мськ*3 + 10	_	ns
SCK $\downarrow \rightarrow$ SOT delay time	t slove	SCK, SOT	External clock	_	2 tмськ*3 + 60	ns
Valid SIN $ ightarrow$ SCK \uparrow	tivshe	SCK, SIN	operation output pin:	30	—	ns
SCK $\uparrow \rightarrow$ valid SIN hold time	t shixe	SCK, SIN	C∟ = 80 pF + 1 TTL	$t_{\text{MCLK}^{*3}} + 30$	—	ns
SCK fall time	t⊧	SCK		_	10	ns
SCK rise time	t _R	SCK		_	10	ns

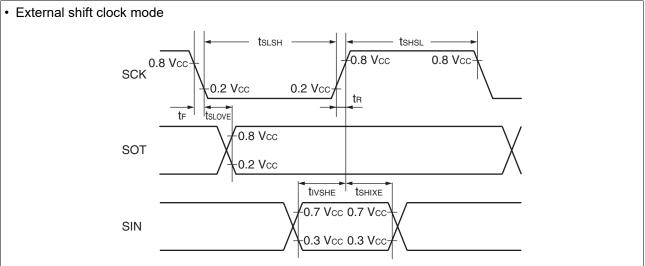
*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See "Source Clock / Machine Clock" for tmclk.







Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is disabled*2. (ESCR register: SCES bit = 1, ECCR register: SCDE bit = 0)

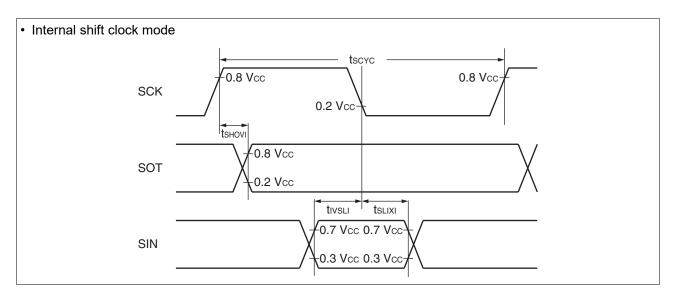
Parameter	Symbol	Pin name	Condition	Va	Unit	
Parameter	Symbol	i in name	Condition	Min	Max	Unit
Serial clock cycle time	t scyc	SCK		5 t MCLK* ³	—	ns
SCK $\uparrow \rightarrow$ SOT delay time	t shovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN $ ightarrow$ SCK \downarrow	tivsli	SCK, SIN	operation output pin: C∟ = 80 pF + 1 TTL	t мськ*3 + 80	—	ns
SCK $\downarrow \rightarrow$ valid SIN hold time	tslixi	SCK, SIN		0	—	ns
Serial clock "H" pulse width	t shsl	SCK		$3 \ t_{\text{MCLK}^{\star 3}} - t_{\text{R}}$	—	ns
Serial clock "L" pulse width	t _{SLSH}	SCK		t мськ*3 + 10	—	ns
SCK $\uparrow \rightarrow$ SOT delay time	t shove	SCK, SOT	External clock	_	$2 t_{\text{MCLK}^{*3}} + 60$	ns
Valid SIN $ ightarrow$ SCK \downarrow	tivsle	SCK, SIN	operation output pin:	30	—	ns
SCK $\downarrow \rightarrow$ valid SIN hold time	t slixe	SCK, SIN	C∟ = 80 pF + 1 TTL	$t_{\text{MCLK}^{\star3}} + 30$	_	ns
SCK fall time	t⊧	SCK		_	10	ns
SCK rise time	tR	SCK	1		10	ns

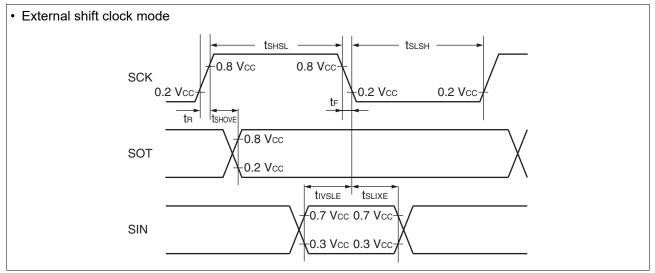
*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

*3: See "Source Clock / Machine Clock" for tmclk.









Sampling is executed at the rising edge of the sampling clock*1, and serial clock delay is enabled*2. (ESCR register: SCES bit = 0, ECCR register: SCDE bit = 1)

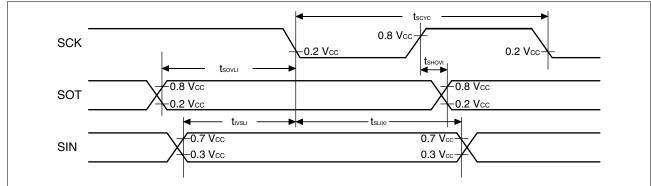
Parameter	Symbol	Pin name	Condition	Va	ue	Unit
Faranneter	Symbol	Fiii lidille	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	—	ns
SCK $\uparrow \rightarrow$ SOT delay time	t shovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN $ ightarrow$ SCK \downarrow	tivsli	SCK, SIN	operation output pin: $C_L = 80 \text{ pF} + 1 \text{ TTL}$	t мськ*3 + 80	_	ns
SCK $\downarrow \rightarrow$ valid SIN hold time	tslixi	SCK, SIN		0	_	ns
$SOT o SCK \downarrow delay$ time	tsovli	SCK, SOT		$3 \ t_{\text{MCLK}^{\star 3}} - 70$		ns

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ V}_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function that delays the output signal of the serial clock for half clock.

*3: See "Source Clock / Machine Clock" for tmclk.



Sampling is executed at the falling edge of the sampling clock^{*1}, and serial clock delay is enabled^{*2}. (ESCR register: SCES bit = 1, ECCR register: SCDE bit = 1)

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$

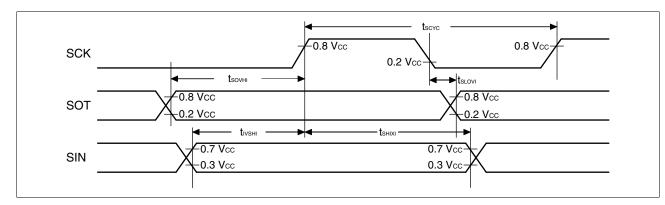
Parameter	Symbol	Pin name	Condition	Va	Unit	
Farameter	Symbol	Fin name	Condition	Min	Мах	Unit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³		ns
SCK $\downarrow \rightarrow$ SOT delay time	t slovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN $ ightarrow$ SCK \uparrow	tıvsнı	SCK, SIN	operating output pin: C∟ = 80 pF + 1 TTL	t мськ*3 + 80	_	ns
SCK $\uparrow \rightarrow$ valid SIN hold time	tsнixi	SCK, SIN		0	_	ns
$SOT o SCK \uparrow delay$ time	tsovнı	SCK, SOT		$3 \ t_{\text{MCLK}^{\star 3}} - 70$		ns

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function that delays the output signal of the serial clock for half clock.

*3: See "Source Clock / Machine Clock" for tmclk.





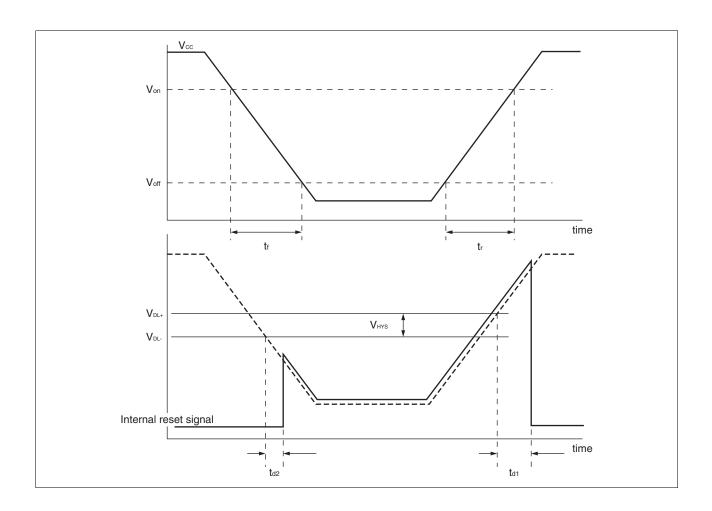
24.4.7 Low-voltage Detection

(Vss = 0.0 V, T_A = -40 °C to +85 °C)

Parameter	Symbol	Value			Unit	Remarks		
Farameter	Symbol	Min	Тур	Max	Unit	Remarks		
Release voltage*	V _{DL+}	2.52	2.7	2.88	- V			
		2.61	2.8	2.99		At power supply rise		
		2.89	3.1	3.31				
		3.08	3.3	3.52				
Detection voltage*	V _{DL-}	2.43	2.6	2.77	V	At power supply fall		
		2.52	2.7	2.88				
		2.80	3	3.20				
		2.99	3.2	3.41				
Hysteresis width	VHYS	_	100	_	mV			
Power supply start voltage	Voff		_	2.3	V			
Power supply end voltage	Von	4.9	_	_	V			
Power supply voltage change time (at power supply rise)	tr	650	_	_	μs	Slope of power supply that the reset release signal generates within the rating (V_{DL+})		
Power supply voltage change time (at power supply fall)	tr	650	_	_	μs	Slope of power supply that the reset detection signal generates within the rating (V_{DL-})		
Reset release delay time	td₁	_	_	30	μs			
Reset detection delay time	t _{d2}			30	μs			
LVD threshold voltage transition stabilization time	tstb	10			μs			

*: The release voltage and the detection voltage can be selected by using the LVD reset voltage selection ID register (LVDR) in the low-voltage detection reset circuit. For details of the LVDR register, refer to "CHAPTER 18 LOW-VOLTAGE DETECTION RESET CIRCUIT" in "New 8FX MB95560H/570H/580H Hardware Manual".







24.5 A/D Converter

24.5.1 A/D Converter Electrical Characteristics

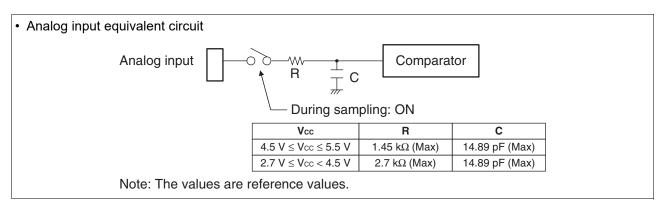
$(V_{\rm CC} = 2.7 \text{ V to } 5.5 \text{ V}, \text{ V}_{\rm SS} = 0.0 \text{ V}, \text{ T}_{\rm A} = -40 \text{ °C to}$						
Parameter	Symbol	Value				Bomorko
	Symbol	Min Typ Max			Unit	Remarks
Resolution		—	—	10	bit	
Total error		-3		+3	LSB	
Linearity error	—	-2.5	—	+2.5	LSB	
Differential linearity error		-1.9	_	+1.9	LSB	
Zero transition voltage	Vот	Vss – 1.5 LSB	Vss + 0.5 LSB	Vss + 2.5 LSB	V	
Full-scale transition voltage	Vfst	Vcc – 4.5 LSB	Vcc – 2 LSB	Vcc + 0.5 LSB	V	
Compare time		1	—	10	μs	$4.5~V \leq V \text{cc} \leq 5.5~V$
		3		10	μs	$2.7~V \leq V_{CC} < 4.5~V$
Sampling time	_	0.6	_	œ	μs	$\begin{array}{l} \text{2.7 V} \leq V_{CC} \leq 5.5 \text{ V},\\ \text{with external}\\ \text{impedance} < 3.3 \text{ k}\Omega \end{array}$
Analog input current	Iain	-0.3		+0.3	μA	
Analog input voltage	VAIN	Vss		Vcc	V	

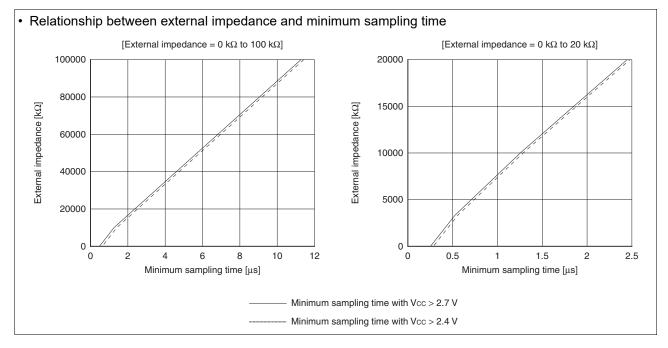


24.5.2 Notes on Using A/D Converter

• External impedance of analog input and its sampling time

The A/D converter of the MB95560H/570H/580H has a sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the capacitor of the internal sample and hold circuit is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, considering the relationship between the external impedance and minimum sampling time, either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. In addition, if sufficient sampling time cannot be secured, connect a capacitor of about 0.1 μ F to the analog input pin.





A/D conversion error

As $|V_{CC} - V_{SS}|$ decreases, the A/D conversion error increases proportionately.



24.5.3 Definitions of A/D Converter Terms

Resolution

٠

It indicates the level of analog variation that can be distinguished by the A/D converter.

When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

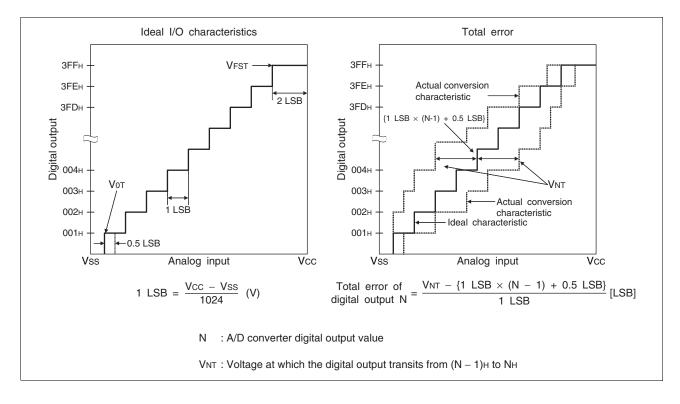
• Linearity error (unit: LSB)

It indicates how much an actual conversion value deviates from the straight line connecting the zero transition point ("000000000" $\leftarrow \rightarrow$ "0000000001") of a device to the full-scale transition point ("1111111111" $\leftarrow \rightarrow$ "111111110") of the same device.

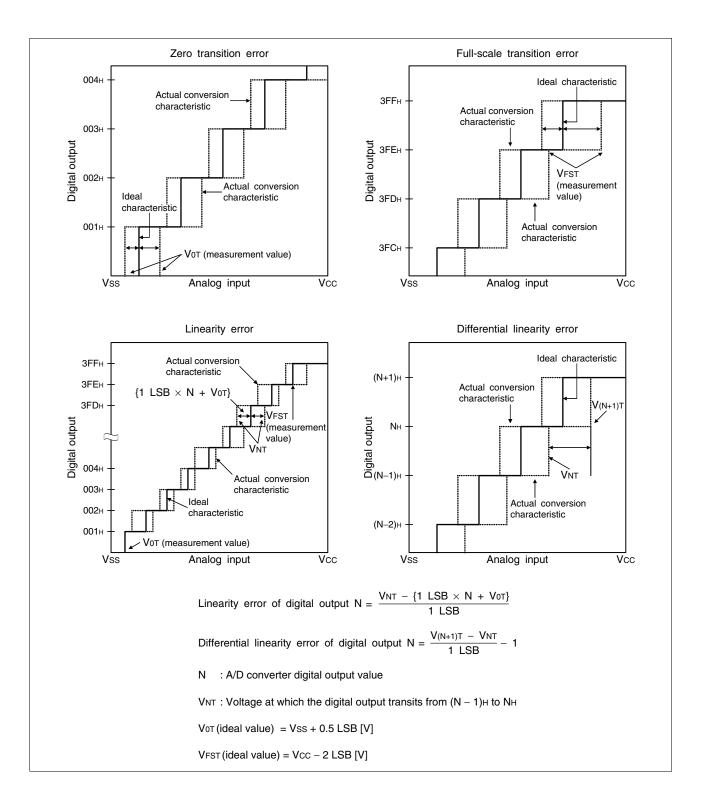
• Differential linear error (unit: LSB)

It indicates how much the input voltage required to change the output code by 1 LSB deviates from an ideal value. Total error (unit: LSB)

It indicates the difference between an actual value and a theoretical value. The error can be caused by a zero transition error, a full-scale transition errors, a linearity error, a quantum error, or noise.









24.6 Flash Memory Program/Erase Characteristics

Parameter		Value		Unit	Remarks	
Farameter	Min	Тур	Мах	Unit		
Sector erase time (2 Kbyte sector)	—	0.3* ¹	1.6* ²	s	The time of writing 00⊦ prior to erasure is excluded.	
Sector erase time (16 Kbyte sector)	_	0.6*1	3.1* ²	s	The time of writing 00⊦ prior to erasure is excluded.	
Byte writing time	—	17	272	μs	System-level overhead is excluded.	
Program/erase cycle	100000	_	—	cycle		
Power supply voltage at program/erase	2.4	_	5.5	V		
Flash memory data retention time	5* ³	_	_	year	Average T _A = +85 °C	

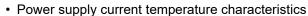
*1: Vcc = 5.5 V, T_A = +25 °C, 0 cycle

*2: Vcc = 2.4 V, T_A = +85 °C, 100000 cycles

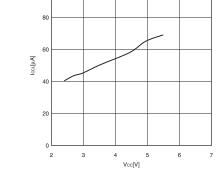
*3: This value was converted from the result of a technology reliability assessment. (The value was converted from the result of a high temperature accelerated test using the Arrhenius equation with an average temperature of +85 °C).



25. Sample Characteristics

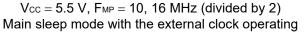


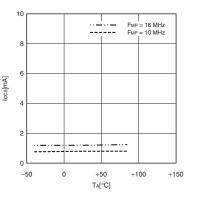
Icc - Vcc $T_A = +25 \text{ °C}, F_{MP} = 2, 4, 8, 10, 16 \text{ MHz}$ (divided by 2) Main clock mode with the external clock operating FMP = 16 MHz _ _ _ FMP = 10 MHz FMP = 8 MHz FMP = 4 MHz 15 FMP = 2 MHz loc[mA] 10 . __ . . __ . -------------------7 2 3 5 6 Vcc[V] $I_{\text{CCS}} - V_{\text{CC}}$ $T_A = +25 \text{ °C}, F_{MP} = 2, 4, 8, 10, 16 \text{ MHz}$ (divided by 2) Main sleep mode with the external clock operating FMP = 16 MHz FMP = 10 MHz FMP = 8 MHz FMP = 4 MHz FMP = 2 MHz .._.!_ ____ lccs[mA] -----3 5 6 7 Vcc[V] $I_{\text{CCL}} - V_{\text{CC}}$ $T_A = +25 \text{ °C}, F_{MPL} = 16 \text{ kHz} \text{ (divided by 2)}$ Subclock mode with the external clock operating



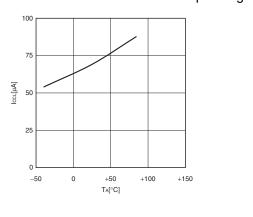
 $Icc - T_A$ $V_{CC} = 5.5 \text{ V}, \text{ F}_{MP} = 10, 16 \text{ MHz} \text{ (divided by 2)}$ Main clock mode with the external clock operating ···<u>·</u>··<u>-</u> FMP = 16 MHz FMP = 10 MHz 15 loc[mA] 10 _.._. · · · - · · · · 0 0 +50 -50 +100+150T_A[°C]



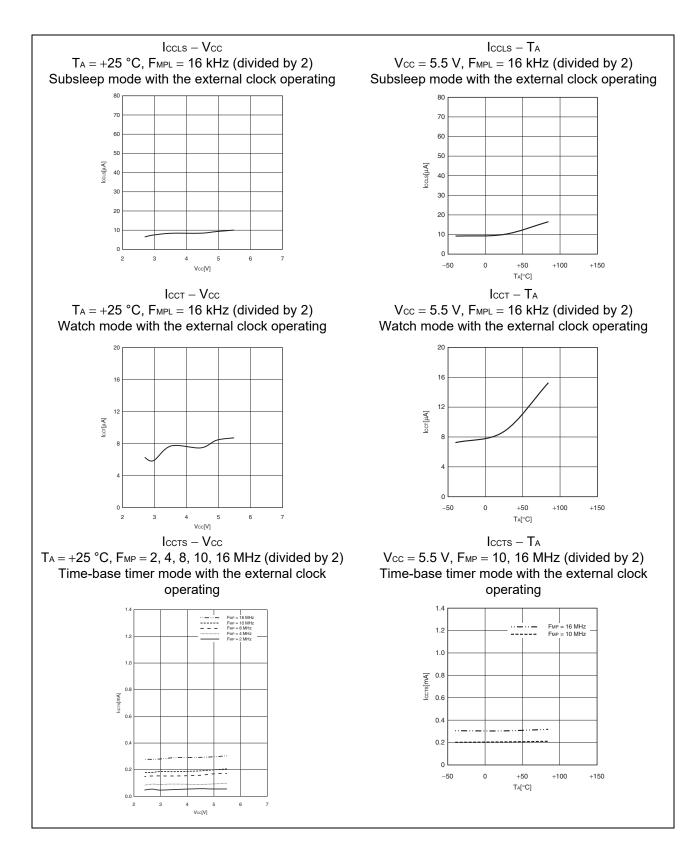




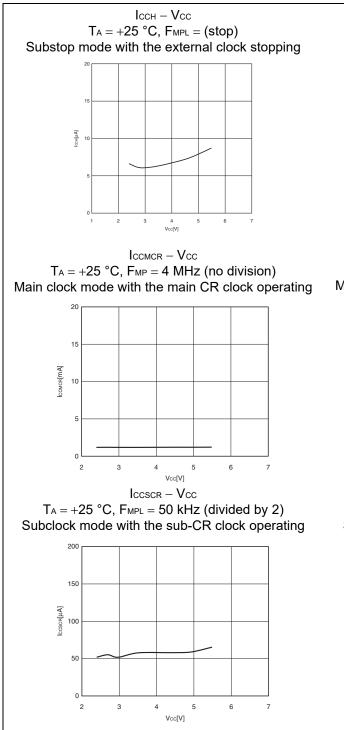
 $I_{CCL} - T_A$ Vcc = 5.5 V, F_{MPL} = 16 kHz (divided by 2) Subclock mode with the external clock operating

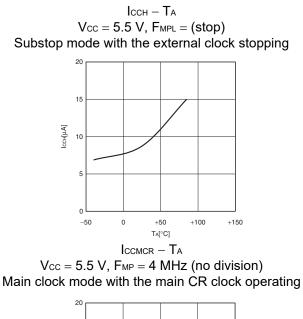


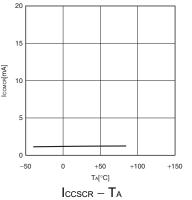


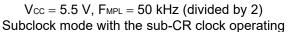


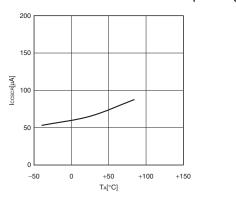






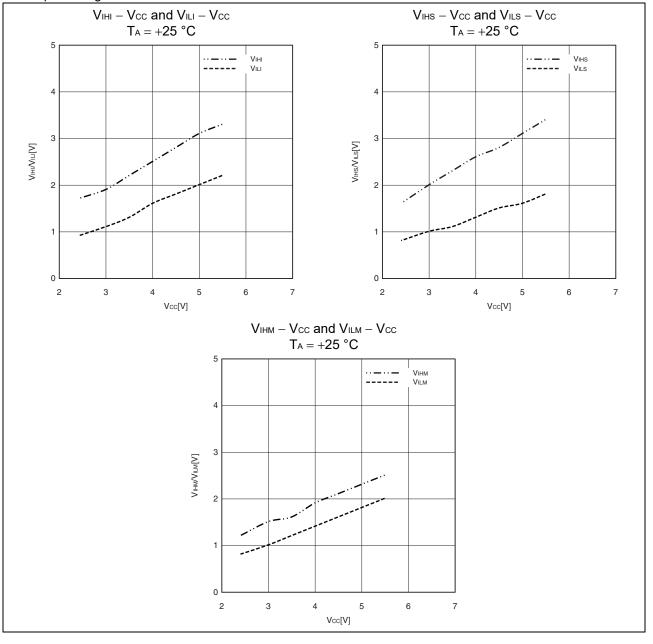






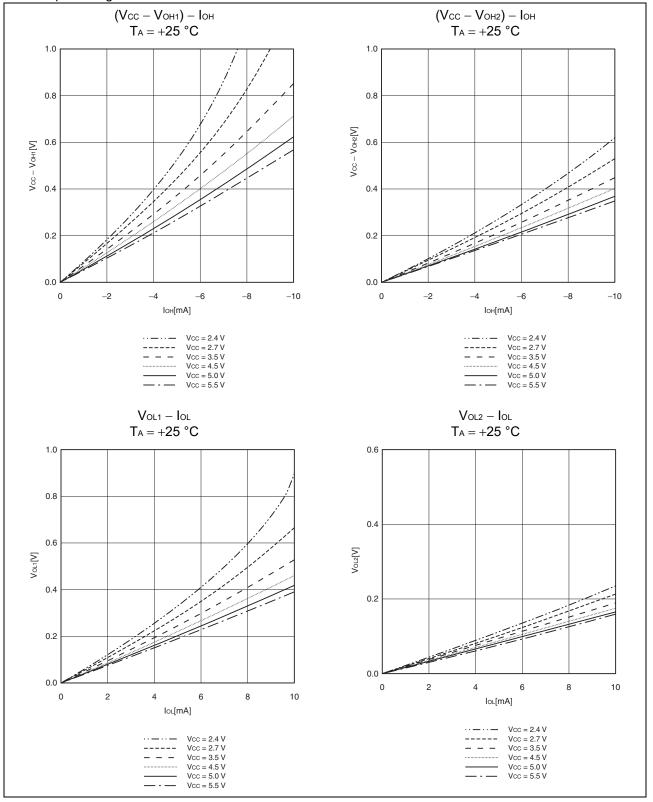


Input voltage characteristics



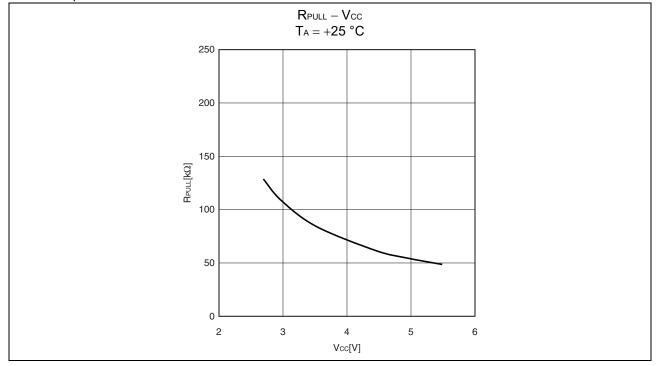


Output voltage characteristics





• Pull-up characteristics





26. Mask Options

		MB95F562H MB95F563H	MB95F562K MB95F563K
	Part Number	MB95F564H	MB95F564K
		MB95F572H	MB95F572K
		MB95F573H	MB95F573K
No.		MB95F574H	MB95F574K
		MB95F582H	MB95F582K
		MB95F583H	MB95F583K
		MB95F584H	MB95F584K
	Selectable/Fixed	Fixed	
1	Low-voltage detection reset	Without low-voltage detection reset	With low-voltage detection reset
2	Reset	With dedicated reset input	Without dedicated reset input



27. Ordering Information

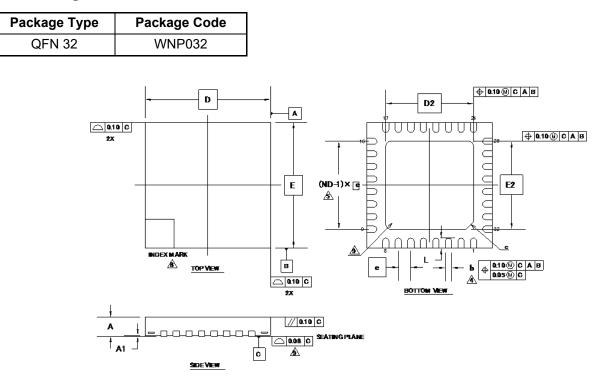
Part number	Package	Packing
MB95F562HWQN-G-SNE1 MB95F562KWQN-G-SNE1 MB95F563HWQN-G-SNE1 MB95F563KWQN-G-SNE1 MB95F564HWQN-G-SNE1 MB95F564KWQN-G-SNE1	32-pin plastic QFN	Tray
MB95F562HWQN-G-SNERE1 MB95F562KWQN-G-SNERE1 MB95F563HWQN-G-SNERE1 MB95F563KWQN-G-SNERE1 MB95F564HWQN-G-SNERE1 MB95F564KWQN-G-SNERE1	(WNP032)	Reel
MB95F562HPF-G-SNE2 MB95F562KPF-G-SNE2 MB95F563HPF-G-SNE2 MB95F563KPF-G-SNE2 MB95F564HPF-G-SNE2 MB95F564KPF-G-UNE2	20-pin plastic SOP (SOJ020)	Tube
MB95F562HPFT-G-SNE2 MB95F562KPFT-G-SNE2 MB95F563HPFT-G-SNE2 MB95F563KPFT-G-SNE2 MB95F564HPFT-G-SNE2 MB95F564KPFT-G-UNE2	20-pin plastic TSSOP (STG020)	Tube
MB95F562KPFT-G-UNERE2 MB95F563HPFT-G-UNERE2 MB95F563KPFT-G-UNERE2 MB95F564KPFT-G-UNERE2		Reel
MB95F582HWQN-G-SNE1 MB95F582KWQN-G-SNE1 MB95F583HWQN-G-SNE1 MB95F583KWQN-G-SNE1 MB95F584HWQN-G-SNE1 MB95F584KWQN-G-SNE1	32-pin plastic QFN	Tray
MB95F582HWQN-G-SNERE1 MB95F582KWQN-G-SNERE1 MB95F583HWQN-G-SNERE1 MB95F583KWQN-G-SNERE1 MB95F584HWQN-G-SNERE1 MB95F584KWQN-G-SNERE1	(WNP032)	Reel
MB95F582HPFT-G-SNE2 MB95F582KPFT-G-SNE2 MB95F583HPFT-G-SNE2 MB95F583KPFT-G-SNE2 MB95F584HPFT-G-SNE2 MB95F584KPFT-G-SNE2	16-pin plastic TSSOP (STB016)	Tube



Part number	Package	Packing
MB95F582HPF-G-SNE2 MB95F582KPF-G-SNE2 MB95F583HPF-G-SNE2 MB95F583KPF-G-SNE2 MB95F584HPF-G-SNE2 MB95F584KPF-G-SNE2	16-pin plastic SOP (SO016)	Tube
MB95F572HPH-G-SNE2 MB95F572KPH-G-SNE2 MB95F573HPH-G-SNE2 MB95F573KPH-G-SNE2 MB95F574HPH-G-SNE2 MB95F574KPH-G-SNE2	8-pin plastic DIP (PDA008)	Tube
MB95F572HPF-G-SNE2 MB95F572KPF-G-SNE2 MB95F573HPF-G-SNE2 MB95F573KPF-G-SNE2 MB95F574HPF-G-SNE2 MB95F574KPF-G-SNE2	8-pin plastic SOP (SOD008)	Tube



28. Package Dimension



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
•	—		0.80
A1	0.00		0.05
D	5.00 BSC		
E	5.00 BSC		
ь	0.18 0.25 0.30		
D2	3.50 BSC		
E2	:	3.50 BSC	
е		0.50 BSC	
C	0.30 REF		
L	0.35 0.40 0.45		

NOTE

1. ALL DIMENSIONS ARE IN MILLIMETERS

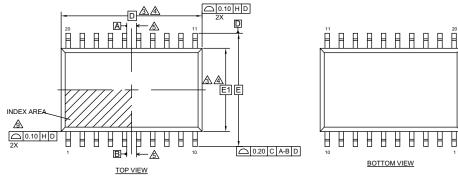
- 2. DIMENSIONING AND TOLERANCING CONFORMS TO ASME Y14.5-1994.
- 3. N IS THE TOTAL NUMBER OF TERMINALS.
- ▲ DIMENSION Ъ "APPLIES TO METALLIZED TERMINALAND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL TPIF THE TERMINAL HAS THE OPTIONAL RADIUS ON THE OTHEREND OF THE TERMINAL THE DIMENSION Ъ "SHOULD NOT BE MEASURED IN THAT RADIUSAREA.
- **<u>A</u>ND REFER TO THE NUMBER OF TERMINALS ON D OR ESIDE.**
- 6. MAX. PACKAGEWARPAGE IS 0.05mm.
- 7. MAXIMUM ALLOWABLE BURRS IS 0.076mm IN ALL DIRECTIONS.
- ▲ PIN #1 ID ON TOP WILL BE LOCATED WITHIN INDICATED ZONE
- (A), BILA TERAL COPLANARITY ZONE APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.
- 10. JEDEC SPECIFICATION NO. REF : N/A

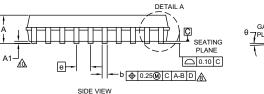
PÁCKÁSE OUTLINE, 32 LEÁD GEN 3.003.000 SM N WINF032 3.50, 5M N EPÁD (SÁMN) REVSK

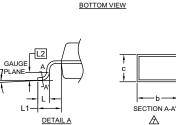
002-15160 **



Package Type	Package Code	
SOP 20	SOJ020	







SYMBOL	DIMENSIONS			
STINIBUL	MIN.	NOM.	MAX.	
А	—	—	2.65	
A1	0.05	—	0.20	
D	12.70 BSC			
E	10.20 BSC			
E1	7.50 BSC			
θ	0°	—	8°	
с	0.22		0.32	
b	0.35	0.40	0.49	
L	0.50 0.80 1.27			
L 1	1.35 REF			
L 2	0.25 BSC			
е	1.27 BSC			

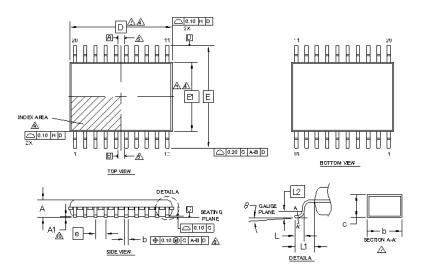
NOTES

- 1. ALL DIMENSIONS ARE IN MILLIMETER.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- DIMENSIONING D INCLUDE MOLD FLASH, DIMENSIONING E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.025 mm PER SIDE. D and E1 DIMENSION ARE DETERMINED AT DATUM H.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONING D and E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, THE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- A DATUMS A & B TO BE DETERMINED AT DATUM H.
- "N" IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH.
- THE DIMENSION APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm TO 0.25mm FROM THE LEAD TIP.
- ▲ DIMENSION "b" DOES NOT INCLUDE THE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10mm TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. THE DAMBAR MAY NOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.
- THIS CHAMFER FEATURE IS OPTIONAL. LF IT IS NOT PRESENT, THEN A PIN 1 IDENTIFIER MUST BE LOCATED WITHIN THE INDEX AREA INDICATED
- A "A1" IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY EXCLUDING THE LID AND OR THERMAL ENHANCEMENT ON CAVITY DOWN PACKAGE CONFIGURATIONS.
- 11. JEDEC SPECIFICATION NO. REF : N/A

002-16348 **



Package Type	Package Code	
TSSOP 20	STG020	



DIMENSONS			
MIN.	NOM.	MAX.	
—	—	1.20	
0.05	—	0.15	
6	5.50BSC		
6	5.40 BSC		
	4.40BSC		
0*	—	8*	
0.10	—	0.19	
0.20	0.24	0.28	
0.45	0.60	0.75	
1.00 REF			
0.25 BSC			4
0.65 BSC			
	MIN. 0.05 6 0.05 0.05 0.00 0.10 0.20 0.45	MIN. NOM. 0.05 0.05 0.05 0.10 0.20 0.24 0.40 0.25 ESC	NDM. NDM. MAX.

- NOTES 1. ALL DIMENSIONS ARE IN MILLIMETER.
- 2. DIMENSIONING AND TOLERANCING PER. ASVE 114.5M 1994.
- DIMENSIONING DI INCLUDE MOLD FLASH, DIMENSIONING ET DOES NOT INCLUDE INTERI FAD FLASH OR PROTRUSION. INTERI FAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.025 mm PER SIDE. D and E1 DIVENSION ARE DETERMINED AT DATUM II.

▲ THE PACKAGE I OP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONING D and ET ARE DEFERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, THE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

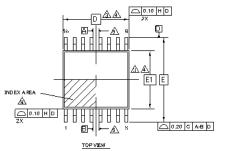
- ▲ DATUMS A & B TO BE DETERMINED AT DATUM H.
- "N" IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH.
- THE DIMENSION APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 min TO 0.25mm FROM THE LEAD TIP.
- ▲ DIMENSION "5" DOES NOT INCLUDE THE DAMBAR PROTRUSION. ALLOW/ABLE DAVBAR PROTRUSION SHALL BE 0.10mm TOTAL IN EXCESS OF THE "5" DIMENSION AT MAXIMUM MATERIAL CONDITION. THE DAMBAR MAY NOT BE LOCATED ON THE LOWER RADIUS OF "HE FOOT.
- $\underline{\bigtriangleup}$ This changer feature is opt onal. Let it is not present, then a pin 1 identifier milist be located with n the index area indicated
- A 'AI' IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY EXCLUDING THE UD AND OR THERMAL ENHANCEMENT ON CAVITY DOWN PACKAGE CONFIGURATIONS. 11. JEDEOSPECIFICATON NO. REF: N/A

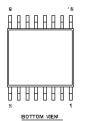
PÁCKÁGE OUTLINE, 20 LEÁD TSSOP 8.50X8.40X1.20 M.N. STG020 REVIX

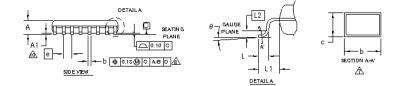
002-15916 **



Package Type	Package Code	
TSSOP 16	STB016	







SYMBOL	DIMENSONS				
SIMBLE	MIN.	NOM.	MAX.		
A	_	—	120		
A1	0.05	—	0.15		
D	4	4.96 BSC			
E	ŧ	6.40B9C			
E 1	4.40BSC				
8	0*	—	8°		
c	0.10	—	0.19		
ь	0.16	0.24	0.32		
L	0.45	0.45 0.60 0.75			
L 1	1.00 REF				
L 2	0.25 BSC				
e	0.65 BSC				

NOTES 1. ALL DIMENSIONS ARE IN MILLIMETER.

2. DIMENSIONING AND TOLERANCING PER-ASVE M14.5M 1994.

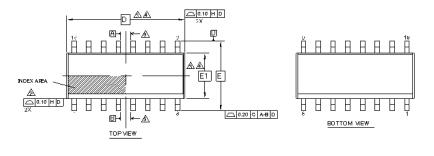
- DIMENSIONING D INCLUDE MOLD FLASH. DIMENSIONING E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.025 Into PER SIDE. D and E1 DIVENSION ARE DETERMINED AT DATUM II.
- ▲ THE PACKAGE I OP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONING D and ET ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOTOFTASH. THE DAR BURKE, GATTE BURKE AND INTERLAD FLASH, BUTTINGLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- A DATUMS A & B TO BE DETERMINED AT DATUM H.
- 0. 'N' IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH.
- THE DIMENSION APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 min TO 0.25mm FROM THE LEAD TIP.
- TO 0.25mm FROM THE LEAD THP. ▲ DIMENSION "15" DOES NOT INCLUDE THE DAMBAR PROTRUSION. ALLOW/ABLE DAVBAR PROTRUSION STIALL BE 0.10mm TOTAL IN EXCESS OF THE "5" DIMENSION AT MAXIMUM MATERIAL CONDITION. THE DAMBAR MAY NOT BE LOCATED ON THE LOWER RADIUS OF "HE FOOT.
- ATHIS CHAMPER FEATURE IS OPT ONAL. LE IT IS NOT PRESENT. THEN A PIN 1 LICENTIFIER MITST BE LOCATED WITH NITHE INDEX AREA INDICATED
- A 'AI' IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY EXCLUDING THE LID AND OR THERMAL ENHANCEMENT ON CAVITY DOWN PACKAGE CONFIGURATIONS. 11. JEDEOSPECIFICATON NO. REF: N/A

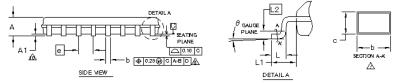
PÁCKÁGE OUTLINE, 18 LEÁD TSSOP 4 99008.4000.1.20 M.M. STEÓ 18. FEV#4

002-15914 **



Package Type	Package Code	
SOP 16	SO016	





SYMEOL	DIMENSONS		
STWEDE	MIN.	NOM.	MAX.
A	—	—	175
A1	0.10		025
D		9.96 BSC	
E	6	5.00 BSC	
E 1	3.90BSC		
8	0*	—	8°
c	0.13		0.20
ь	0.36	0.40	0.51
L	0.45 0.50 0.80 1.05 REF		0.80
L 1			
∟ 2	0.25 BSC		
e	1.27 BSC		

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETER.

2. DIMENSIONING AND TOLERANCING PER-ASVE 114.5M 1994.

DIMENSIONING DINCLUDE MOLD FLASH, DIMENSIONING ET DOES NOT INCLUDE INTERI FAD FLASH OR PROTRUSION, INTERI FAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.925 Imm PER SIDE. D and ET DIVENSION ARE DETERMINED AT DATUM IT.

▲ THE PACKAGE TOP NAY BE SMALLER THAN THE PACKAGE BOTTOM. DIMENSIONING D and E1 ARE DETERMINED AT THE OUTERMOST PATTERNES OF THE PI ASTIC BODY PACIUS/VF OF MOTOFTASH, THE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

ADATUMS A & B TO BE DETERMINED AT DATUM H.

- 'N' IS THE MAXIMUM NUMBER OF TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH.
- THE DIMENSION APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 min TO 0.25mm FROM THE LEAD TIP.
- ▲ DIMENSION '5' DOES NOT INCLUDE THE DAMBAR PROTRUSION. ALLOWABLE DAVBAR PROTRUSION SHALL BE 0.10mm TOTAL IN EXCESS OF THE '5' DIMENSION AT MARKING MATERIAL CONDITION. THE DAMBAR MAY NOT BE LOCATED ON THE LOWER RADIUS OF "HE FOOT.
- THE VANDAR MAY NOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. THIS CHAVIFER FEATURE IS OPT ONAL LF IT IS NOT PRESENT. THEN A PIN 1 IDENTIFIER MINT BE LOCATED WITH N THE INDEX AREA INDICATED
- A 'A1' IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY EXCLUDING THE UD AND OR THERMAL ENHANCEMENT ON CAY TY DOWN PACKAGE CONFIGURATIONS.

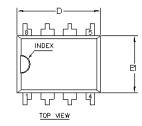
PACKAGE OUTLINE, 18 LEAD SOP 9.96X8.00X1.75 MIN SO018 REVAK

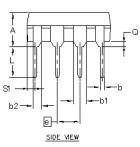
002-15861 **





Package Type	Package Code
DIP 8	PDA008







NOTES 1. ALL DIMENSIONS ARE IN MILLIMETER. 2. JEDEO SPECIFICATION NO . REF : N/A

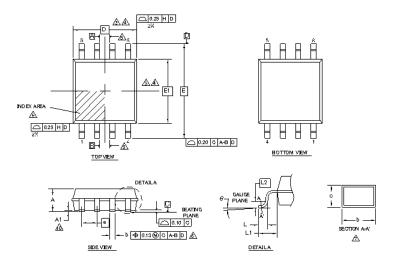
SYMBOL	DIMENSIONS		
SIMBOL	MIN.	NOM.	MAX.
A	—	—	4.36
L	3.00	—	—
D	9.10	9.40	9.80
E	7.62 TYP		
E1	6.10	6.35	6.60
8	—	—	15°
c	0.20	0.25	0.30
ь	0.38	0.46	0.54
b1	—	1.52	1.82
b2	—	0.99	1.29
e	2.54 TYP		
S1	0.59	0.89	1.24
Q	0.50	—	—

PÁCKÁGE ÚUTLINE, 8 LEÁD PDIP 9.40X8.35X3.88 M N PDÁ008 REV%

002-16909 **



Package Type	Package Code
SOP 8	SOD008



SYMEOL	DIMENSION		
SIMBUL	MIN.	NOM.	MAX.
A	—	—	2.10
A1	0.05	—	0.25
D	5.24BSC		
E	7.80BSC		
E 1	5.30BSC		
6	0°	—	8*
c	0.15	—	0.25
b	0.38	0.43	0.48
L	0.55	0.75	0.85
L 1	1.25 REF		
L 2	0.25 BSC		
e	1.27 BSC		

NOTES 1. ALL DIMENSIONS ARE IN MILLIMETER .

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.

▲ DIMENSIONING DINCLUDE VOLD FLASH, DIMENSIONING ET DOES NOT INCLUDE INTERLEAD FLASH OR PROTEVISION. INTERLEAD FLASH OR PROTEVISIONS SHALL NOT EXCEED 9.025 Inter PER SIDE. Dand ET DIMENSION ARE DETERMINED AT DATUM IT.

▲ THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. DIVENSIONING D and ET ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE 11 ASTIC BODY FXCI USINE OF MOTO FT ASH, THE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUTTOLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

▲ DATUVS A & B TO BE DETERMINED AT DATUM H. 6. "V": 3 THE MAXIMUM NUMBER OF TERMINAL POSITIONS FOR THE SPECIFIED PACKAGE LENGTH.

THE DIMENSION APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 min TO 0.20mm FROM THE LEAD TIP.

▲ DIMENSION "b" DOES NOT INCLUDE THE DAVBAR PROTRUSION. ALLOWABLE DANBAR PROTRUSION STALL BE 0.10mm TOTAL IN EXCESS OF THE "o" DIMENSION AT MAXIMUM MATERIAL CONDITION. THE DAMBAR MAY NOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

THIS CHAMFER FEATURE IS OPTIONALL LF IT IS NOT PRESENT. THEN A PIN 1 IDENTIFIER M.IST BE LOCATED WITHIN THE INDEX AREA INDICATED

AT THE DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY EXCLUDING THE JD AND OR THERMAL ENHANCEMENT ON CAVITY DOWN PACKAGE CONFIGURATIONS. 11. EDEGSFECTIONTON IN. FET: N/A

> PÁCKÁGE OUTLINE, 8 LEÁD SOP 5.24X7.80X2.10 MIN SOD008 REV##

002-15858 **



29. Major Changes In This Edition

Spansion Publication Number: DS702-00010

Page	Section	Details
		Changed the series name. MB95560H Series \rightarrow MB95560H Series
—	—	Added information on the MB95570H Series.
		Added information on the MB95580H Series.
27	PIN CONNECTIONDBG pin	Revised details of "• DBG pin".
	• RST pin	Revised details of "• RST pin".
28	• C pin	Corrected the following statement. The decoupling capacitor for the Vcc pin must have a capacitance larger than Cs. \rightarrow
		The decoupling capacitor for the $V_{\rm CC}$ pin must have a capacitance equal to or larger than the capacitance of Cs.
39	■ I/O MAP (MB95570H Series)	Corrected the R/W attribute of the CMDR register. R/W \rightarrow R
		Corrected the R/W attribute of the WDTH register. R/W \rightarrow R
		Corrected the R/W attribute of the WDTL register. R/W \rightarrow R
42	■ I/O MAP (MB95580H Series)	Corrected the R/W attribute of the CMDR register. R/W \rightarrow R
		Corrected the R/W attribute of the WDTH register. R/W \rightarrow R
		Corrected the R/W attribute of the WDTL register. R/W \rightarrow R
46	 ELECTRICAL CHARACTERISTICS 1. Absolute Maximum Ratings 	Corrected the rating of the parameter ""L" level total maximum output current". 48 \rightarrow 100
		Corrected the rating of the parameter ""H" level total maximum output current". 48 \rightarrow -100



Page	Section	Details
48	2. Recommended Operating Conditions	Revised note *2. The value is 2.88 V when the low-voltage detection reset is used. \rightarrow The minimum power supply voltage becomes 2.18 V when a product with the low-voltage detection reset is used.
		Corrected the following statement in note *3. The decoupling capacitor for the V _{CC} pin must have a capacitance larger than C _S . \rightarrow The decoupling capacitor for the V _{CC} pin must have a capacitance equal to or larger than the capacitance of C _S .
		Revised the remark in "• DBG/RST/C pins connection diagram".
49	3. DC Characteristics	Revised the remark of the parameter "Input leak current (Hi-Z output leak current)". When pull-up resistance is disabled → When the internal pull-up resistor is disabled
		Renamed the parameter "Pull-up resistance" to "Internal pull-up resistor".
		Revised the remark of the parameter "Internal pull-up resistor". When pull-up resistance is enabled → When the internal pull-up resistor is enabled
53	4. AC Characteristics (1) Clock Timing	Corrected the pin names of the parameter "Input clock rising time and falling time". X0 \rightarrow X0, X0A X0, X1 \rightarrow X0, X1, X0A, X1A



• Major changes from third edition to fourth edition

Page	Section	Details
23 to 26	HANDLING PRECAUTIONS	New section
35	■ I/O MAP (MB95560H Series)	Corrected the R/W attribute of the CMDR register. R/W \rightarrow R
52	 ELECTRICAL CHARACTERISTICS 4. AC Characteristics (1) Clock Timing 	Corrected the operating conditions of FCRH of the parameter "Clock frequency". $0 \ ^{\circ}C \le T_A < +70 \ ^{\circ}C$ \rightarrow $0 \ ^{\circ}C \le T_A \le +70 \ ^{\circ}C$ $+70 \ ^{\circ}C \le T_A \le +85 \ ^{\circ}C$ \rightarrow $+70 \ ^{\circ}C \le T_A \le +85 \ ^{\circ}C$ Corrected the operating conditions of FMCRPLL of the parameter "Clock frequency". $0 \ ^{\circ}C \le T_A < +70 \ ^{\circ}C$ \rightarrow $0 \ ^{\circ}C \le T_A \le +70 \ ^{\circ}C$ $+70 \ ^{\circ}C \le T_A \le +70 \ ^{\circ}C$ $+70 \ ^{\circ}C \le T_A \le +85 \ ^{\circ}C$
68	 A/D Converter A/D Converter Electrical Characteristics 	Corrected the symbol of the parameter "Zero transition voltage". $V_{\text{OT}} \rightarrow V_{\text{OT}}$
69	 5. A/D Converter (2) Notes on Using A/D Converter Analog input equivalent circuit 	Corrected the range of Vcc. 2.7 V \leq Vcc < 5.5 V \rightarrow 2.7 V \leq Vcc < 4.5 V Corrected the values of R. 3.3 k $\Omega \rightarrow$ 1.45 k Ω 5.7 k $\Omega \rightarrow$ 2.7 k Ω
70, 71	5. A/D Converter (3) Definitions of A/D Converter Terms	Corrected the symbol of the zero transition voltage. $V_{0T} \rightarrow V_{0T}$

NOTE: Please see "Document History" about later revised information.



Document History Page

Document Title: MB95560H Series/MB95570H Series/MB95580H Series, New 8FX 8-bit Microcontrollers Document Number: 002-04629				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	-	AKIH	05/27/2013	Migrated to Cypress and assigned document number 002-04629. No change to document contents or format.
*A	5193921	AKIH	03/29/2016	Updated 24.4.3 External Reset Added MB95F564KPF-G-UNE2, MB95F564KPFT-G-UNE2 in "Ordering Information". Updated to Cypress template.
*В	5420206	HTER	02/06/2017	Changed package code as the following in 1.Product Line-up (Page4, 6), 2.Packages And Corresponding Products (Page 7), 4.Pin Assignment (Page 9 to 10), 27.Ordering Information (Page 75 to 76) and 28.Package Dimensions (Page 77 to 83). "LCC-32P-M19" to "WNP032" "FPT-20P-M09" to "SOJ020" "FPT-20P-M09" to "STB010" "FPT-16P-M08" to "STB016" "FPT-16P-M03" to "STB016" "FPT-8P-M03" to "SOD16" "FPT-8P-M08" to "SOD168" "FPT-8P-M08" to "SOD008" Added Part number "MB95F564KPFT-G-UNERE2, MB95F562KPFT-G- UNERE2, MB95F563KPFT-G-UNERE2" in 27.Ordering Information (Page 75). Deleted Part number "MB95F564KPF-G-SNE2, MB95F564KPFT-G-SNE2" in 27.Ordering Information (Page 75).
*C	5761469	AESATP12	06/08/2017	Updated logo and copyright.
*D	5895915	HUAL	09/27/2017	Added Part number "MB95F563HPFT-G-UNERE2" and Packing information in 27.Ordering Information (Page 75).
*E	5972828	HUAL	11/21/2017	Updated Package Dimension: Updated Diagram corresponding to "SOP 20".



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